

ASUS CONFIDENTIAL

MODEL NAME : *Elsa*  
PCB NO : *???*  
ASUS P/N : *???*

Lanai UMA Schematics Document  
uFCPGA Mobile Merom  
Intel Crestline-GM + ICH8M

2007-03-19

REV :1.2(DELL: X02)

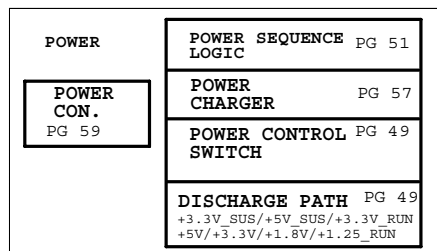
MB PCB	
Part Number	Description
DA800004H0L	PCB 00B LA-3071P REV0 M/B

*BOM NO. ???*  
*PCB P/N: ???*

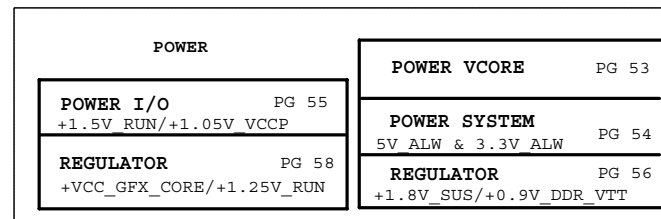
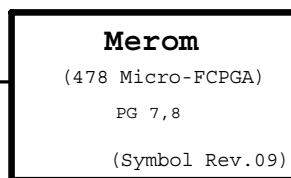
PROJECT:	REVISION	DATE: <i>Monday, March 19, 2007</i>	DESCRIPTION: <i>Cover Page</i>	SCHEMATIC FILE NAME :	DESIGN ENGINEER :
	<i>1.2</i>	SHEET <i>1</i> OF <i>68</i>		RELEASE DATE :	

# LANAI: UMA

**CLOCK**  
CK410M+LP  
PG 21

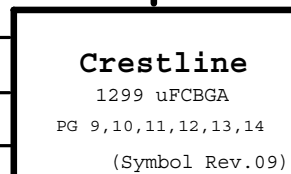


**SDP**  
PG 52



**Panel Connector**  
PG 28

LVDS

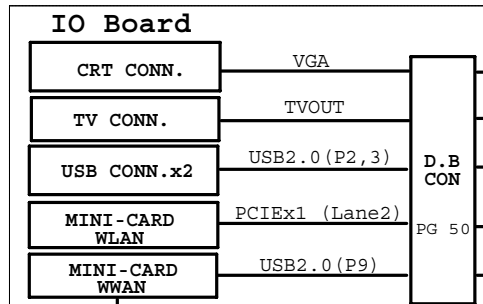


533/667 MHZ DDR II

**DDR2-SODIMM1**  
PG 19

533/667 MHZ DDR II

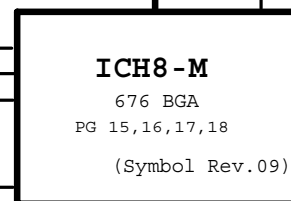
**DDR2-SODIMM2**  
PG 19



DMI INTERFACE

USB2.0 (P0,P1)

**USB CONN.**  
PG 39  
**USB Board**



PCIE (Lane6)

PCI

PCIE (Lane4)

USB2.0 (P6)

USB2.0 (P7)

**CARD READER**  
1394/R5C833  
PG 32,33,34

**BCM5906KMLG**  
QFN-68 PG 47

IHDA

USB2.0 (P5)

**CAMERA**  
PG 28

SATA

**SATA-HDD**  
PG 31

IDE

**CD-ROM**  
PG 31

**EXPRESS-CARD**  
R5538  
PG 35

**RJ45/Magnetic**  
PG 48

**Bluetooth**  
PG 41

SPI

LPC

**SIO**  
MEC5025  
128KB Flash  
TMKBC  
128 Pins VTQFP  
PG 37

**SIO**  
ECE5011  
Expander  
USB 2.0 Hub (4)  
128 Pins VTQFP  
PG 38

BC

**CIR**  
PG 41

**FLASH**  
PG 40

**Touchpad CON.**  
PG 41

**FAN & THERMAL**  
EMC4001  
PG 43

**USER INTERFACE**  
PG 42

**SNIFFER**  
PG 42

**CAPBTN CON.**  
PG 40

**AUDIO/AMP**  
PG 44,45,46

**MDC**  
PG 36

**S/PDIF TO TV CONN.**  
PG 30

**DIGITAL MIC.**  
PG 28

**Speaker CON**  
PG 46

**WtoB CON**  
PG 46

**Audio Jacks \*3**

**JACK Board**

**RJ11**

**RJ11 Board**

PROJECT:

REVISION  
1.2

DATE: Monday, March 19, 2007  
SHEET 2 OF 68

DESCRIPTION:  
BLOCK DIAGRAM

SCHEMATIC FILE NAME:  
RELEASE DATE:

DESIGN ENGINEER:

	A	B	C	D	E
<div>INDEX</div>					
Pg#	Description	DNI LIST	Pg#	Description	DNI LIST
01	Cover Page		63	POWER CIRCUIT CHANGE LIST	
02	Schematic Block Diagram		64	Modem board cover page	
03	INDEX		65	RJ-11 CONN	
04	Bus connection		66	Modem board change List	
05	SMBUS BLOCK		67	USB board cover page	
06	Power Rail		68	USB PORT ( SINGLE * 2 )	
07-08	CPU ( Merom 、 Penryn )				
09-14	Crestline				
15-18	ICH8M				
19-20	DDRII SO-DIMM( 533MHz 、 667MHz )				
21	Clock Generator ( CK410M+LP )				
22-27	BLANK PAGE				
28	LVDS CON & Camera & DMIC				
29	RGB CON				
30	TV OUT CON				
31	SATA(HDD & CD_ROM)				
32-34	MEDIA CARD READER / 1394 ( R5C833 )				
35	PCI-Express Card				
36	MDC CONN				
37	EC ( MEC5025 )				
38	SIO ( ECE5011 )				
39	USB PORT x 2				
40	FLASH & RTC & CAPBTN CONN				
41	TOUCH PAD & BT & CIR & LID				
42	SWITCH & LED				
43	HARDWARE MONITOR ( EMC4001 )				
44-46	AUDIO CODEC & AMP				
47	LOM BCM5906				
48	Magnetics and RJ-45				
49	Power Control Switch				
50	BtoB CON				
51	Power Sequence Logic				
52	XDP				
53-59	Power Circuit				
60	SCREW PAD				
61	Change List 1				
62	Change List 2				
PROJECT: Lanai			REVISION DATE: Monday, March 19, 2007 SHEET 3 OF 68 DESCRIPTION: INDEX		
SCHEMATIC FILE NAME :			DESIGN ENGINEER :		
RELEASE DATE :					
A	B	C	D	E	F

[illegible]

PROJECT: <b>Lanai</b>	REVISION	DATE: <b>Monday, March 19, 2007</b>	DESCRIPTION: <b>INDEX</b>	SCHEMATIC FILE NAME :	DESIGN ENGINEER :
	<b>1.2</b>	SHEET <b>3</b> OF <b>68</b>		RELEASE DATE :	

Footprint Definition	
Resistor	Footprint is 0402 if there is no description
Capacitor	Footprint is 0402 if there is no description
Ferrite Bead	Footprint is 0603 if there is no description

Layout Note
For all of ESD diode, they should be placed as close as possible to connectors and the signals from connectors should be routed to ESD diodes first. There is no branch or via before diodes

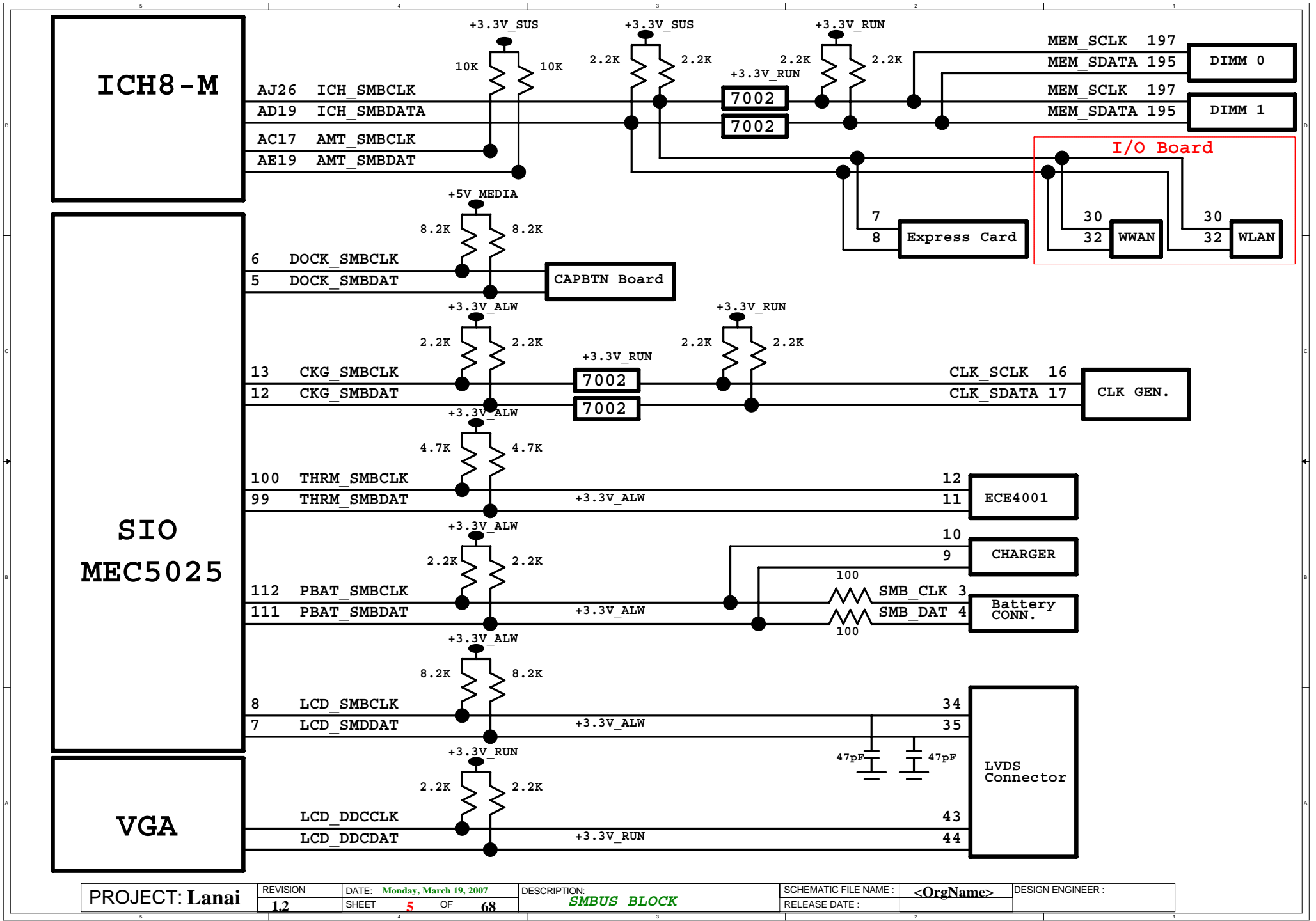
PCI TABLE			
PCI DEVICE	IDSEL	REQ#/GNT#	PIRQ
R5C833	PCI_AD17	PCI_REQ1# PCI_GNT1#	PCI_PIRQC# PCI_PIRQD#

PCI Express TABLE	
Lane 1	WWAN / Mini Card
Lane 2	WLAN / Mini Card
Lane 3	
Lane 4	ExpressCard
Lane 5	
Lane 6	LAN BCM5906KMLG

USB TABLE	
ICH8-0 (EHCI#1)	User1 (Single port , in USB BD)
ICH8-1 (EHCI#1)	User2 (Single port , in USB BD)
ICH8-2 (EHCI#1)	User3 (Dual port-bottom , in I/O BD)
ICH8-3 (EHCI#1)	User4 (Dual port-top , in I/O BD)
ICH8-4 (EHCI#1)	
ICH8-5 (EHCI#1)	Camera
ICH8-6 (EHCI#2)	ExpressCard
ICH8-7 (EHCI#2)	BT Module
ICH8-8 (EHCI#2)	
ICH8-9 (EHCI#2)	WWAN / Mini Card

Note : No USB for WLAN

PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: Bus Connection	SCHEMATIC FILE NAME: <OrgName>	DESIGN ENGINEER:
	1.2	SHEET 4 OF 68			
				RELEASE DATE:	



PROJECT: Lanai

REVISION  
1.2

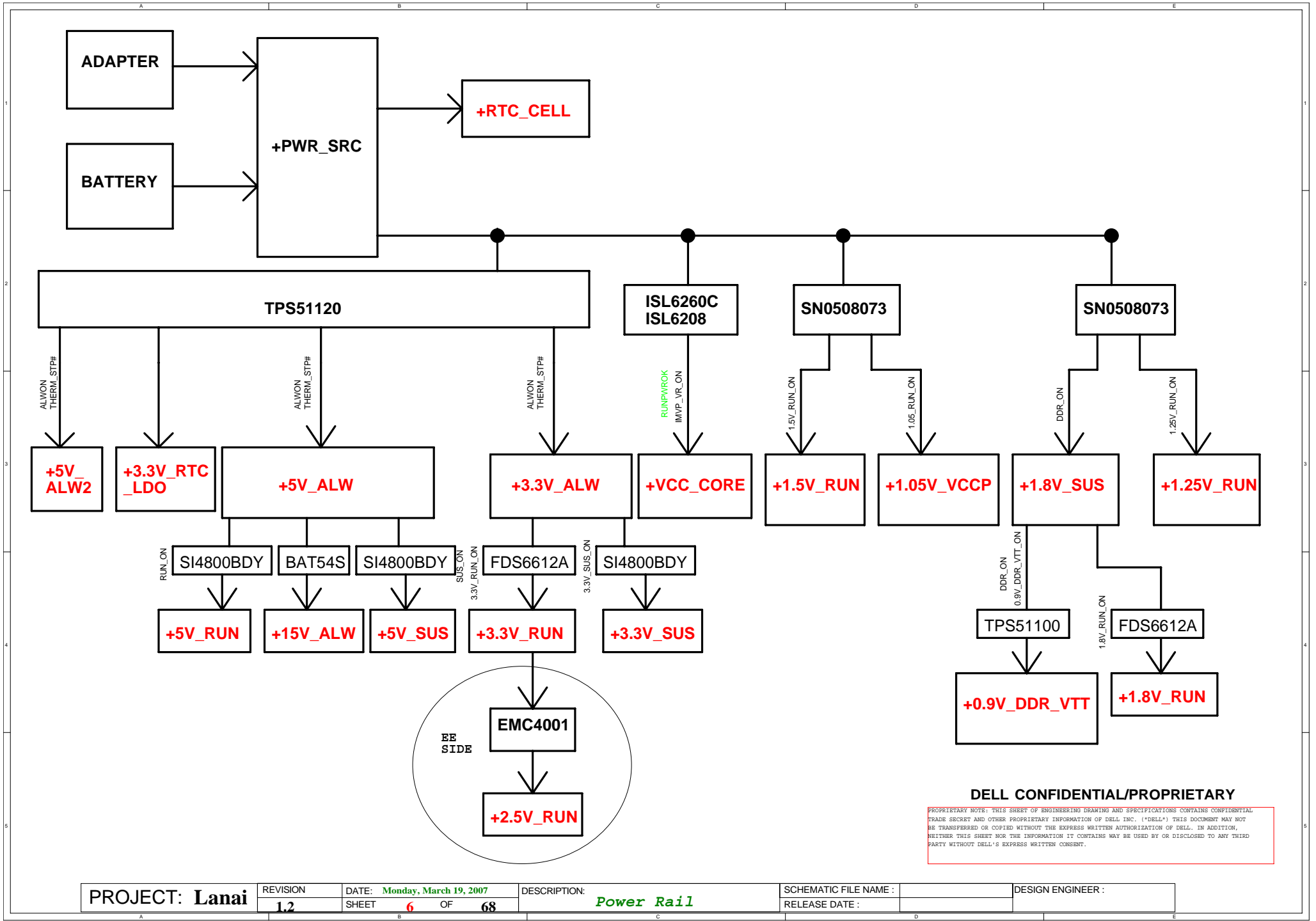
DATE: Monday, March 19, 2007  
SHEET 5 OF 68

DESCRIPTION:  
SMBUS BLOCK

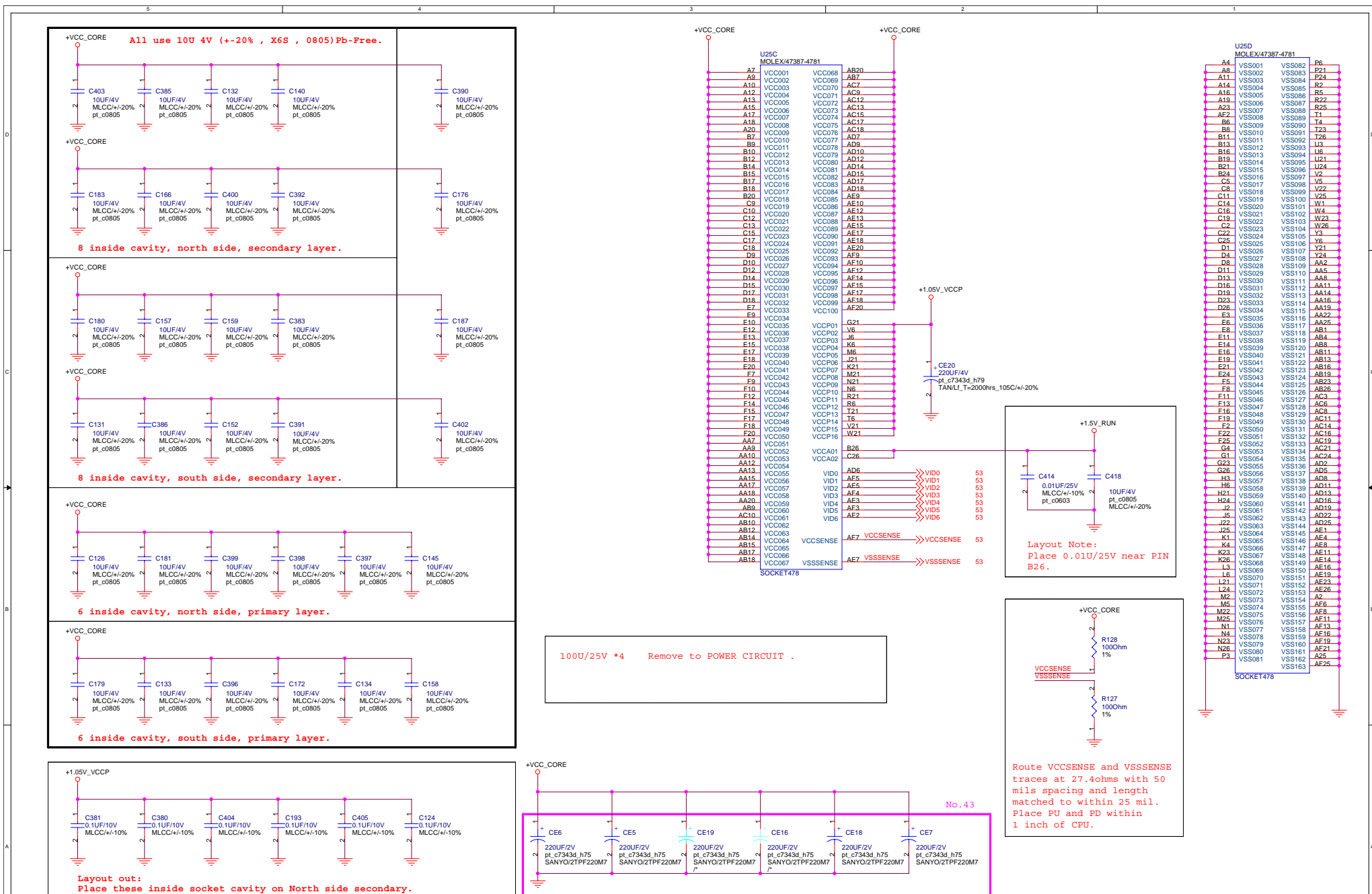
SCHEMATIC FILE NAME :  
RELEASE DATE :

<OrgName>

DESIGN ENGINEER :







PROJECT: Lanai

REVISION  
1.2

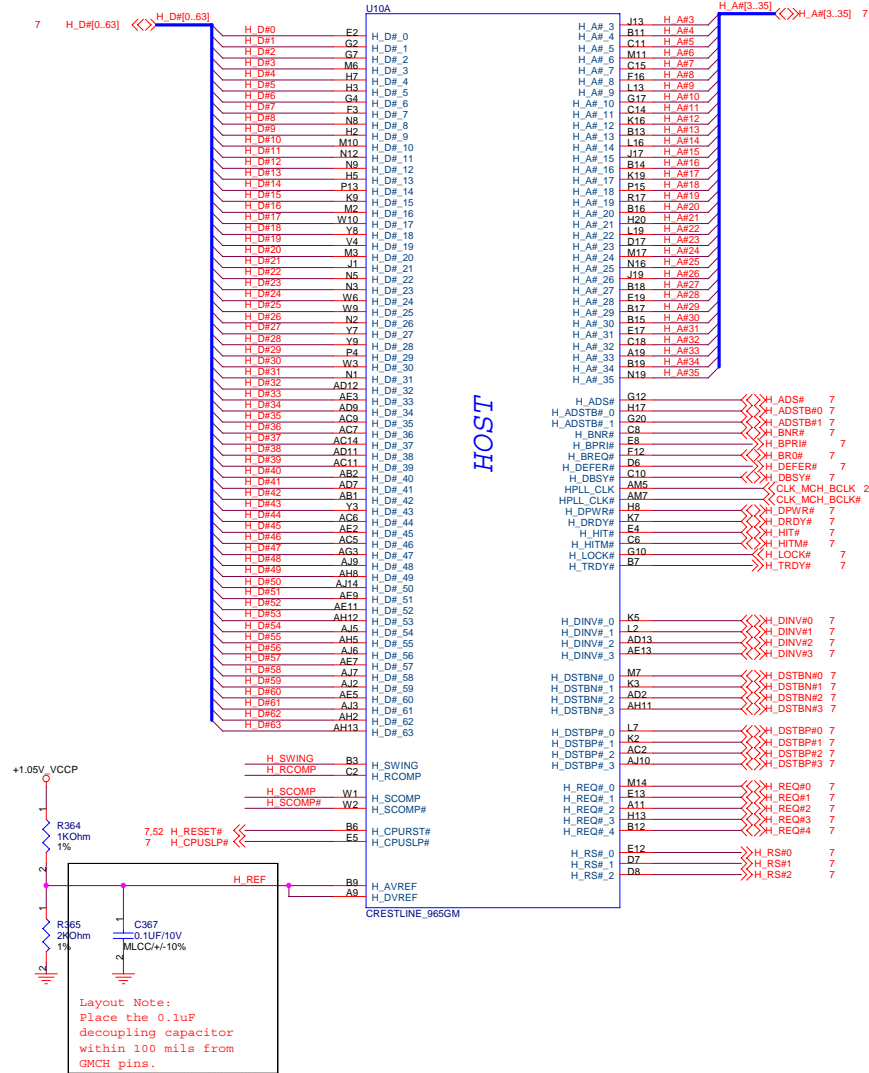
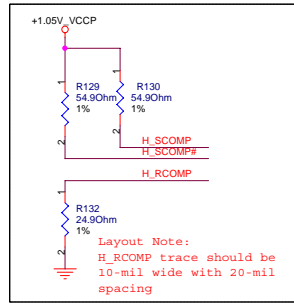
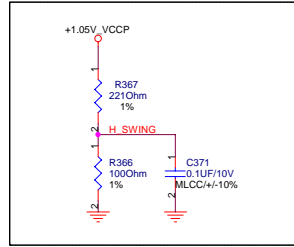
DATE: Monday, March 19, 2007  
SHEET 8 OF 68

DESCRIPTION: Merom CPU (2)

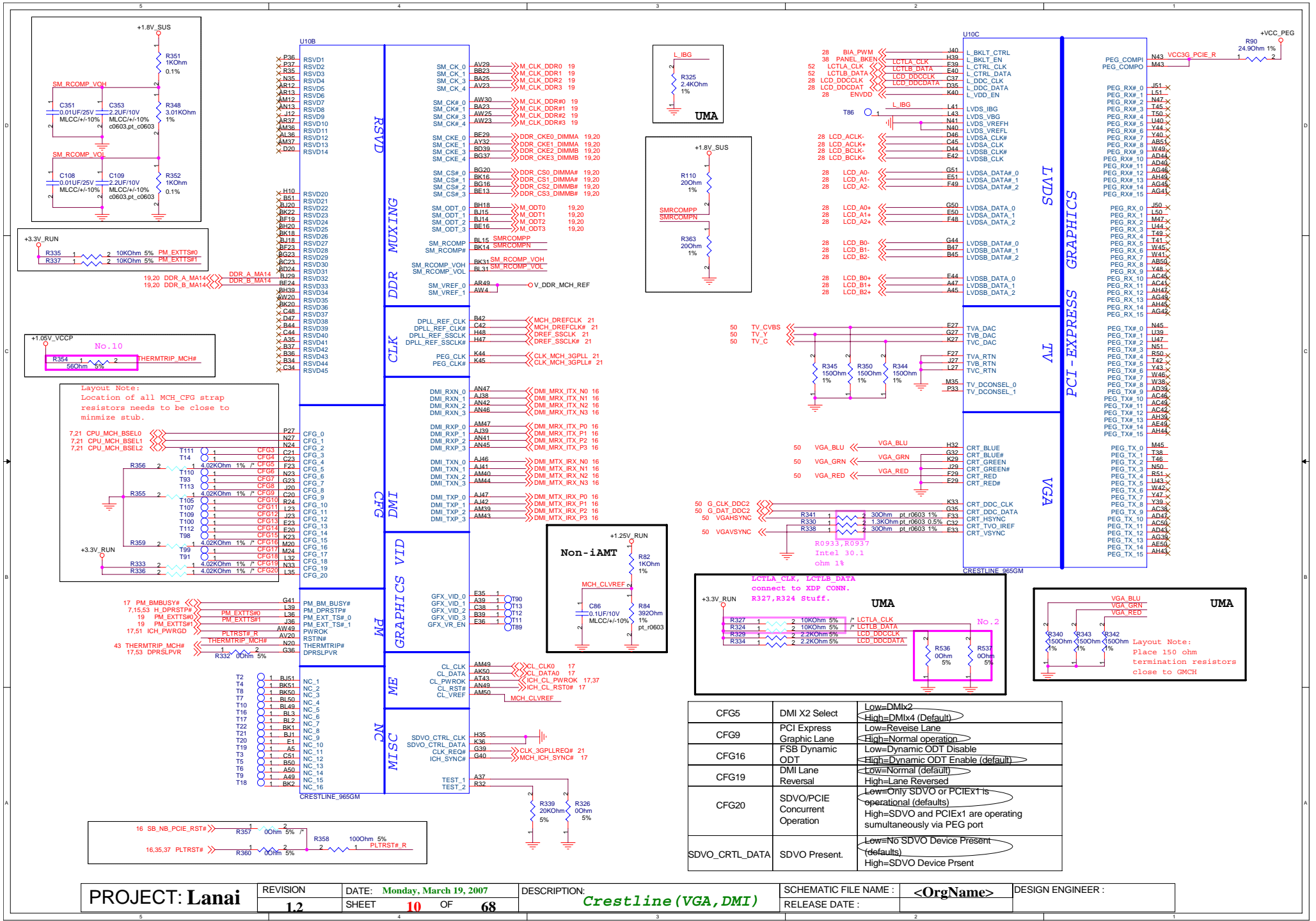
SCHEMATIC FILE NAME: <OrgName>  
RELEASE DATE:

DESIGN ENGINEER:





PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: Crestline (HOST)	SCHEMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER :
	1.2	SHEET 9 OF 68		RELEASE DATE :		



PROJECT: Lanai

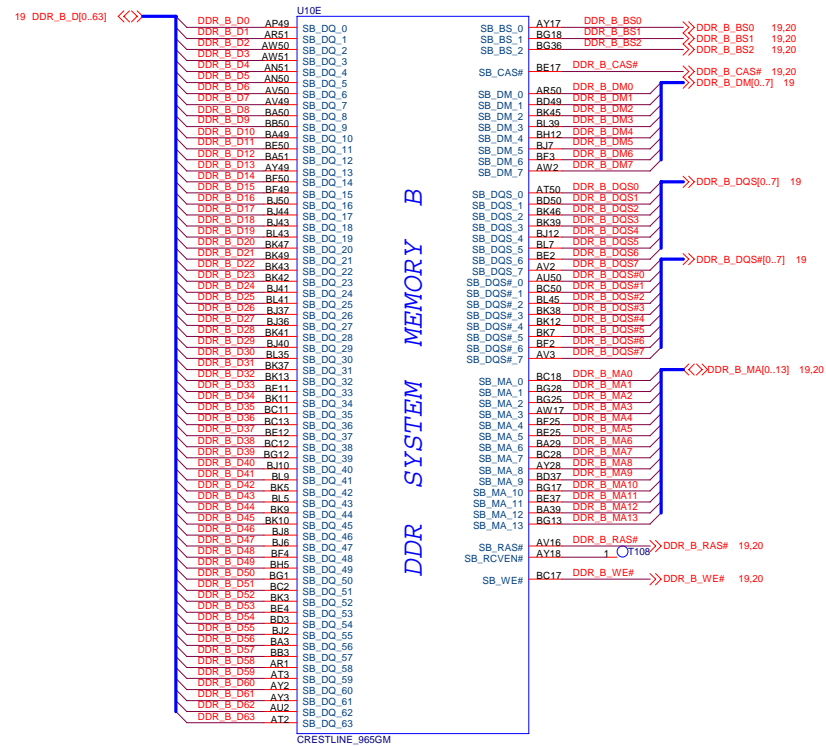
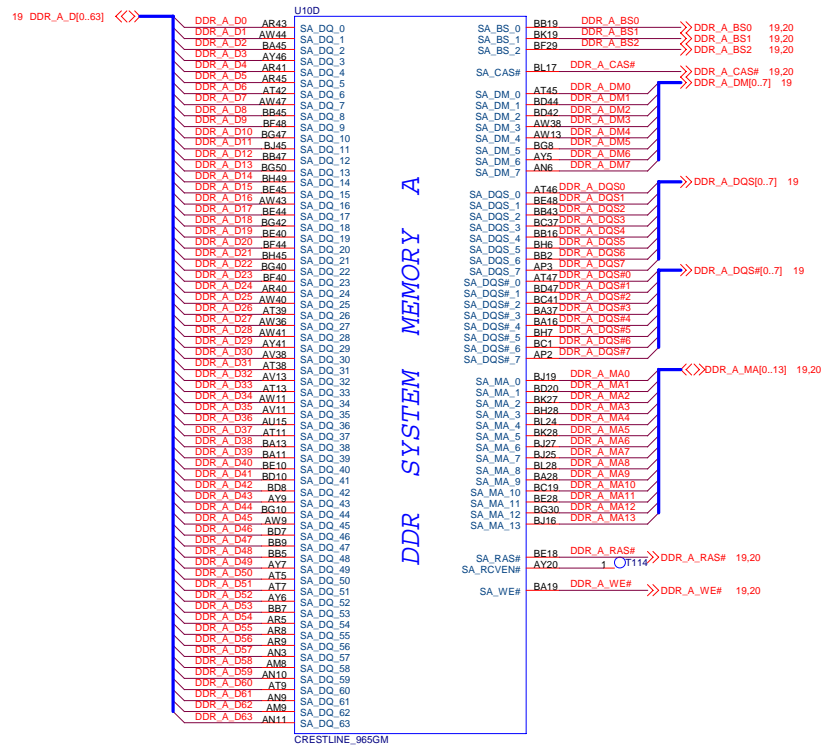
REVISION  
1.2

DATE: Monday, March 19, 2007  
SHEET 10 OF 68

DESCRIPTION: Crestline (VGA, DMI)

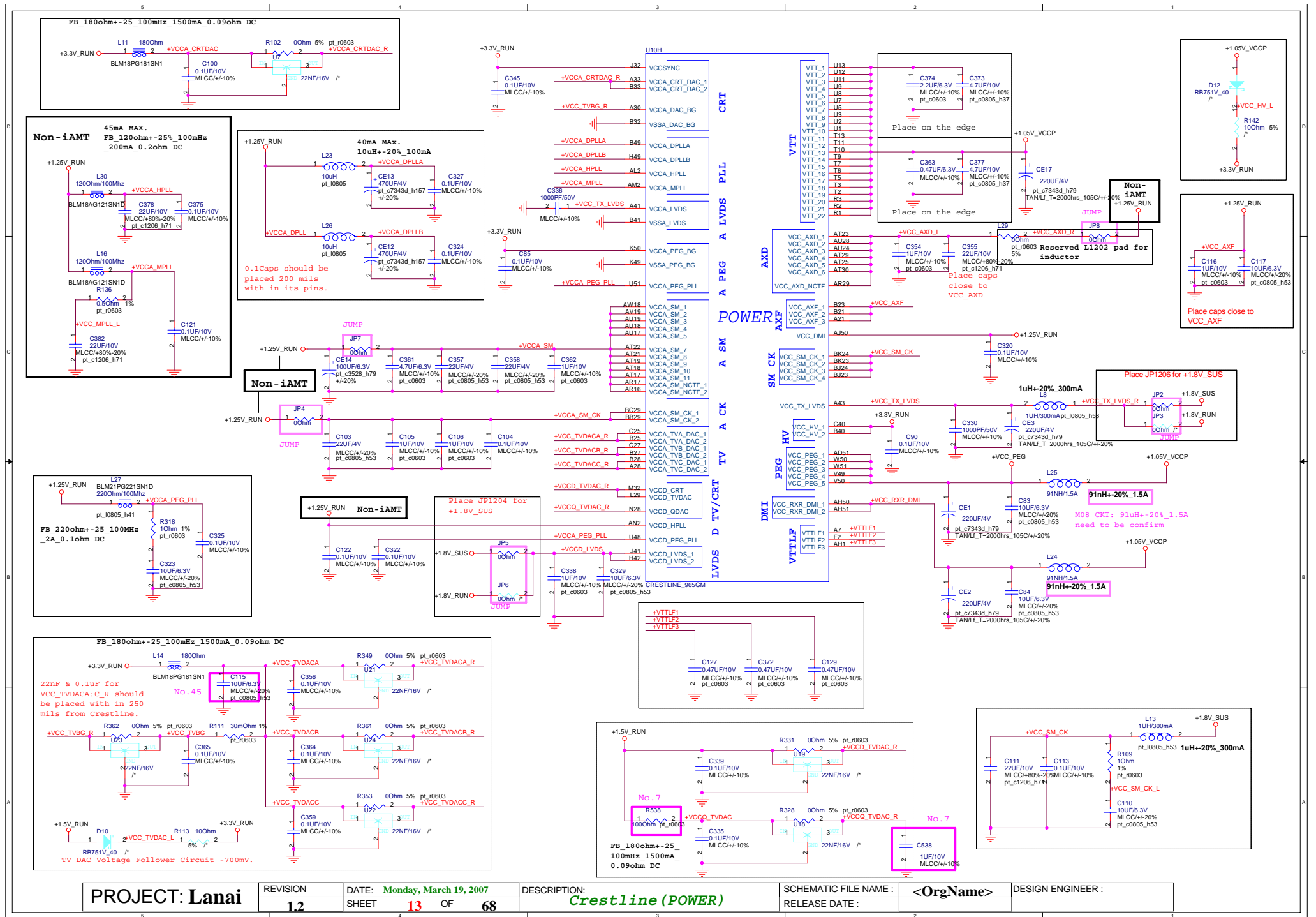
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RELEASE DATE:

DESIGN ENGINEER:



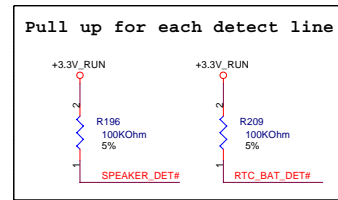
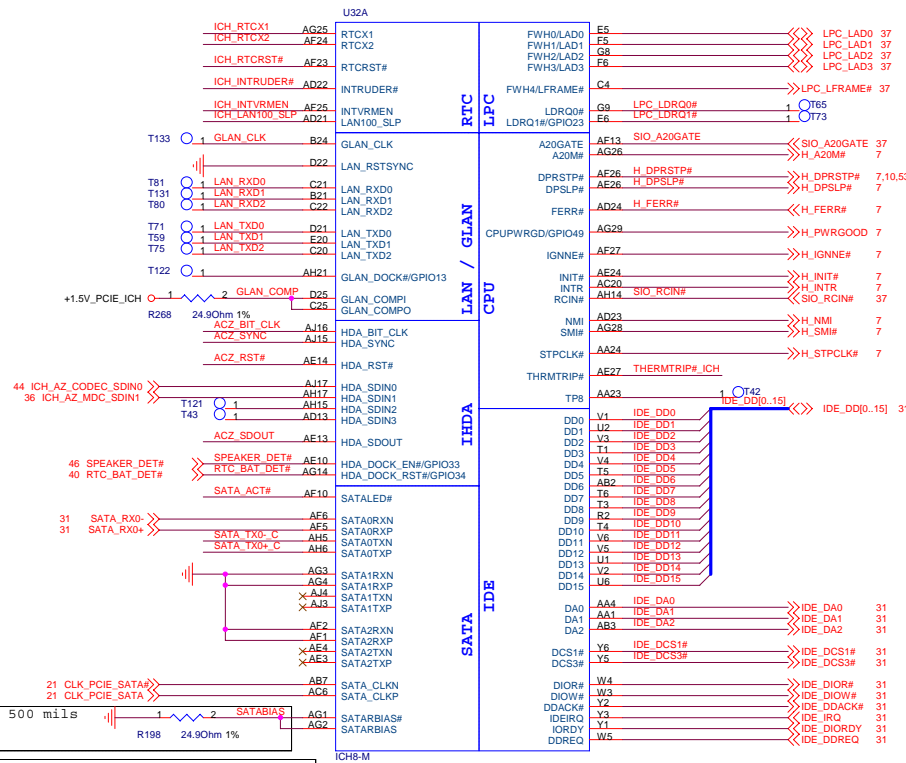
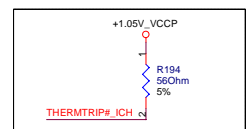
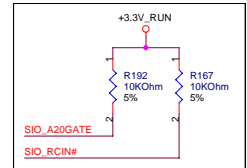
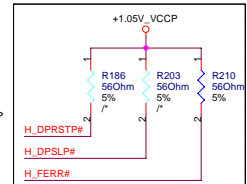
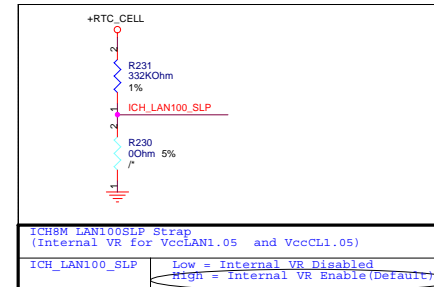
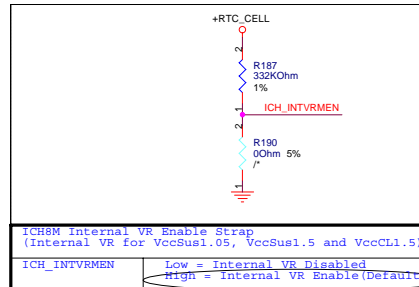
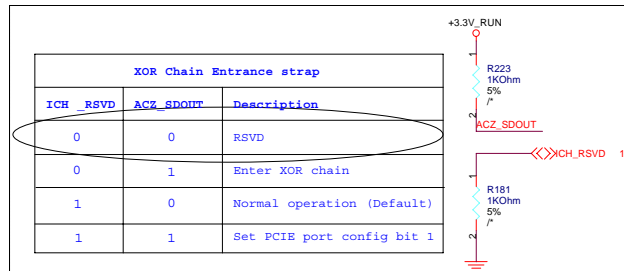
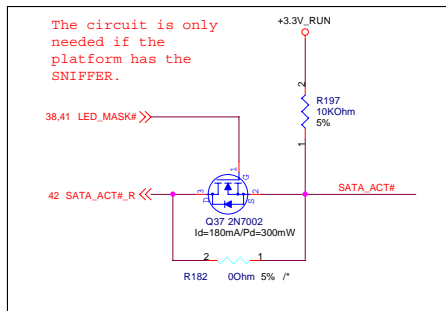
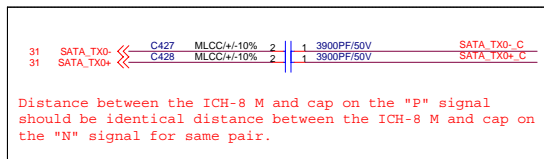
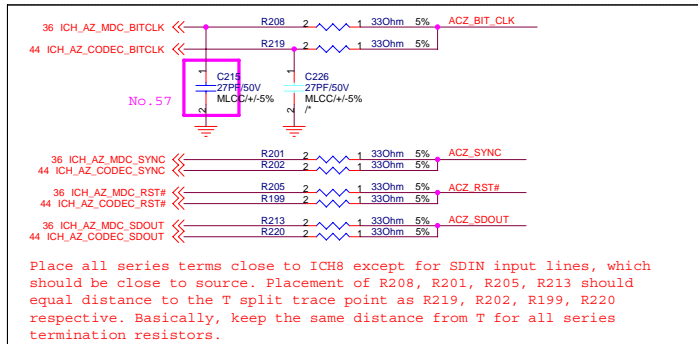
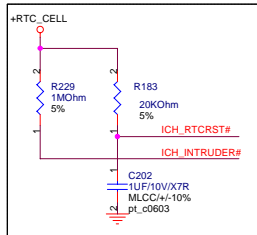
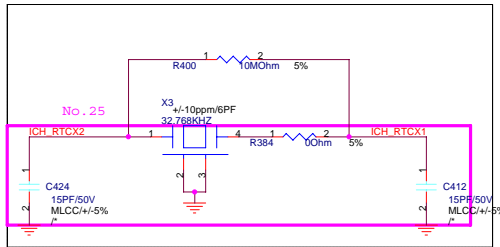
PROJECT: Lanai	REVISION 1.2	DATE: Monday, March 19, 2007	DESCRIPTION: Crestline (DDR2)	SCHEMATIC FILE NAME: <OrgName>	DESIGN ENGINEER:
		SHEET 11 OF 68		RELEASE DATE:	











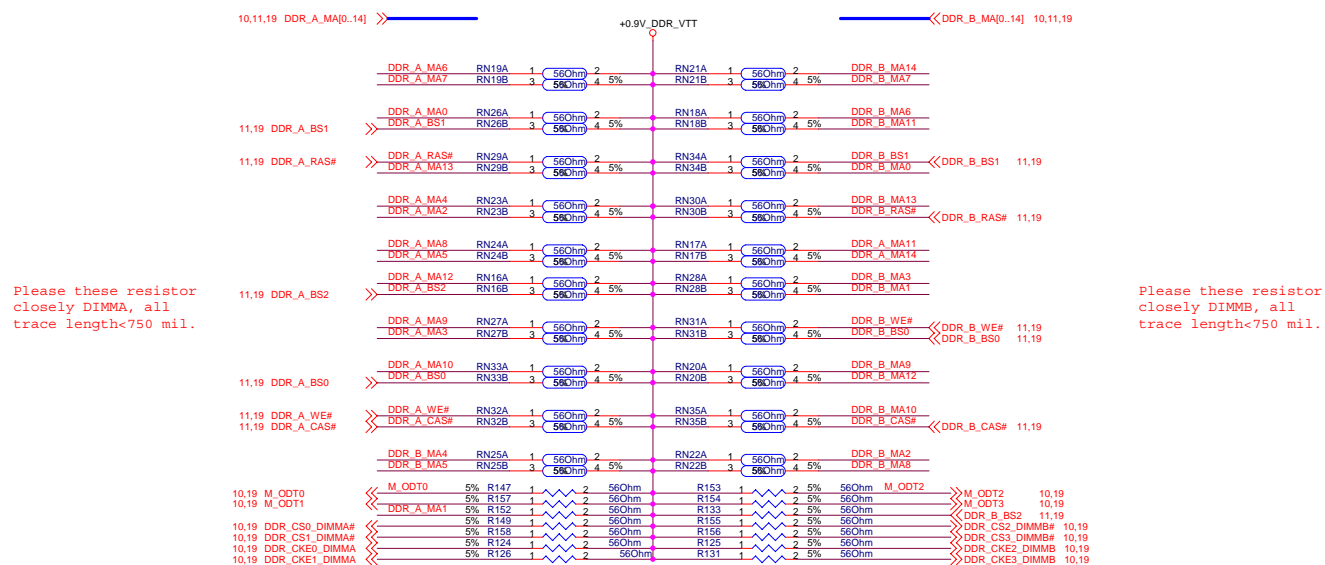
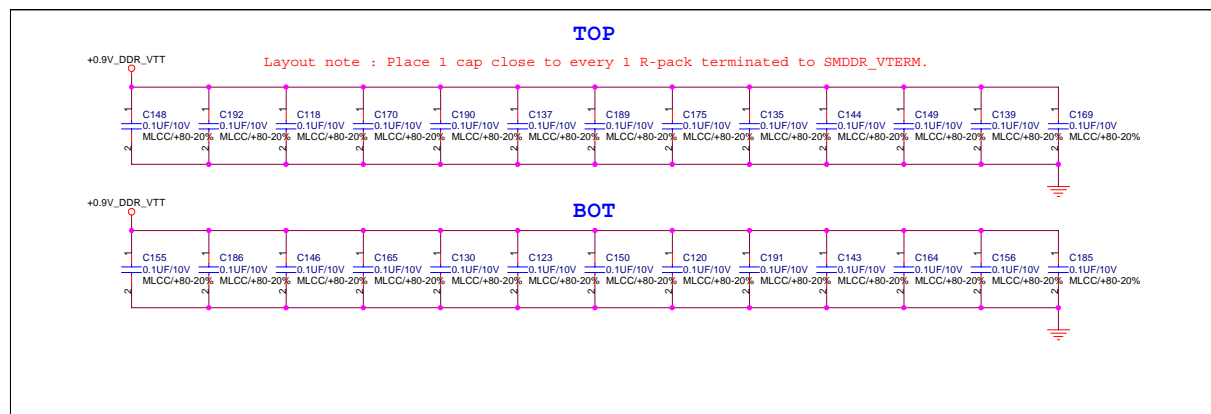












PROJECT: Lanai	REVISION 1.2	DATE: Monday, March 19, 2007 SHEET 20 OF 68	DESCRIPTION: DDR2 SO-DIMM (1)	SCHEMATIC FILE NAME : RELEASE DATE :	<OrgName>	DESIGN ENGINEER :
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PROJECT: <b>Lanai</b>	REVISION	DATE: <b>Monday, March 19, 2007</b>	DESCRIPTION:	SCHMATIC FILE NAME :	<b>&lt;OrgName&gt;</b>	DESIGN ENGINEER :
	<b>1.2</b>	SHEET <b>23</b> OF <b>68</b>		RELEASE DATE :		

5		4		3		2		1	
D									
C									
B									
A									
PROJECT: Lanai									
REVISION		DATE: Monday, March 19, 2007		DESCRIPTION:		SCHEMATIC FILE NAME :		DESIGN ENGINEER :	
12		SHEET 24 OF 68				RELEASE DATE :		<OrgName>	
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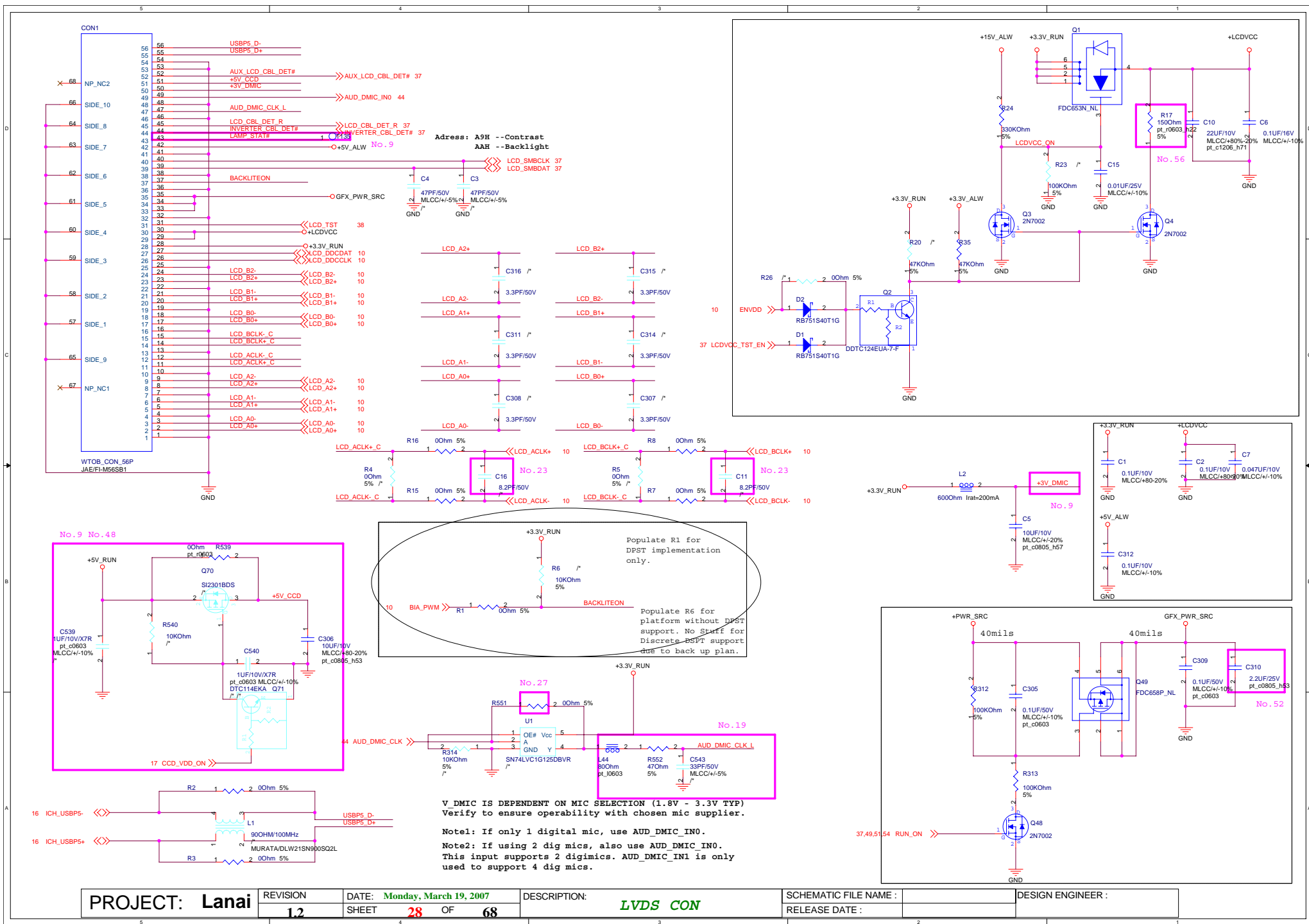


A		B		C		D		E	
1								1	
2								2	
3								3	
4								4	
5								5	
PROJECT: Lanai		REVISION	DATE: Monday, March 19, 2007		DESCRIPTION:		SCHEMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER :
		1.2	SHEET 25 OF 68				RELEASE DATE :		
A		B		C		D		E	



PROJECT: <b>Lanai</b>	REVISION	DATE: <b>Monday, March 19, 2007</b>	DESCRIPTION:	SCHEMATIC FILE NAME :	DESIGN ENGINEER :
	<b>1.2</b>	SHEET <b>27</b> OF <b>68</b>		RELEASE DATE :	

*Sean Kuo*



PROJECT: Lanai

REVISION  
1.2

DATE: Monday, March 19, 2007  
SHEET 28 OF 68

DESCRIPTION: LVDS CON

SCHEMATIC FILE NAME:  
RELEASE DATE:

DESIGN ENGINEER:



---文才专用---

---文才专用---

# SATA Connector

Place caps close to connector.

SATA RXN0\_C MLCC/±10% 2 1 3800PF/50V/X7R C319  
SATA RXN0+ MLCC/±10% 2 2 3800PF/50V/X7R C318  
SATA RXN0- MLCC/±10% 2 2 3800PF/50V/X7R C318  
SATA RXP0\_C MLCC/±10% 2 2 3800PF/50V/X7R C318  
SATA RXP0+ MLCC/±10% 2 2 3800PF/50V/X7R C318  
SATA RXP0- MLCC/±10% 2 2 3800PF/50V/X7R C318

5V\_HDD  
C58 0.1uF/10V/Y5V  
MLCC/±80-20%  
C46 1000PF/50V  
MLCC/±1-10%

CON12  
NP\_NC3 1 25  
NP\_NC1 2 23  
NP\_NC2 3 24  
NP\_NC4 4 26  
SATA\_CON\_22P  
FOXCONN/LD2822H-SA3L6

1 2 3 4 5 6 7  
8 9 10 11 12 13 14 15 16 17 18 19 20 21 22

SATA RXN0\_C  
SATA RXN0+  
SATA RXN0-  
SATA RXP0\_C  
SATA RXP0+  
SATA RXP0-

+3.3V\_RUN  
+5V\_HDD

5V\_ALW  
5V\_HDD  
5V\_ALW2  
15V\_ALW  
HDD\_EN\_5V  
HDDC\_EN  
5V\_RUN

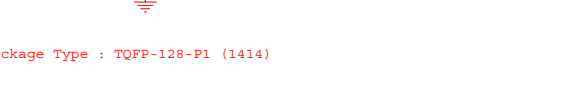
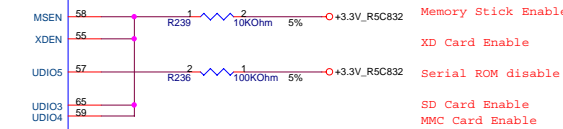
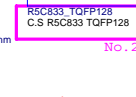
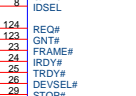
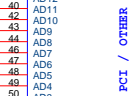
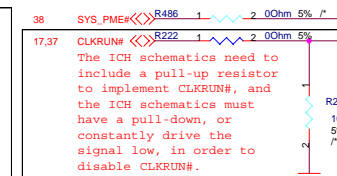
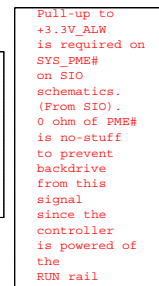
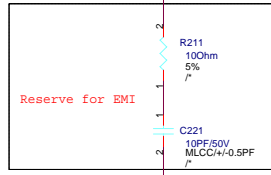
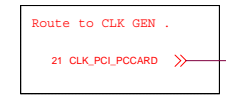
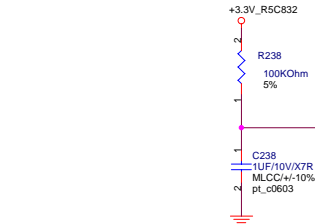
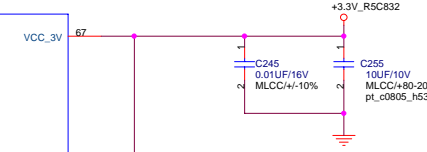
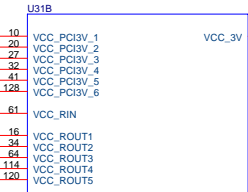
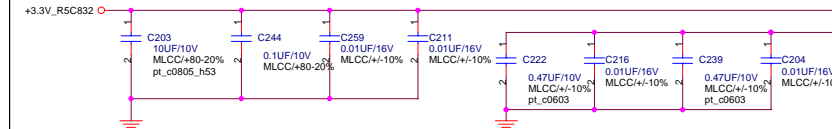
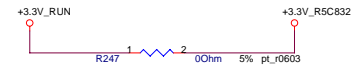
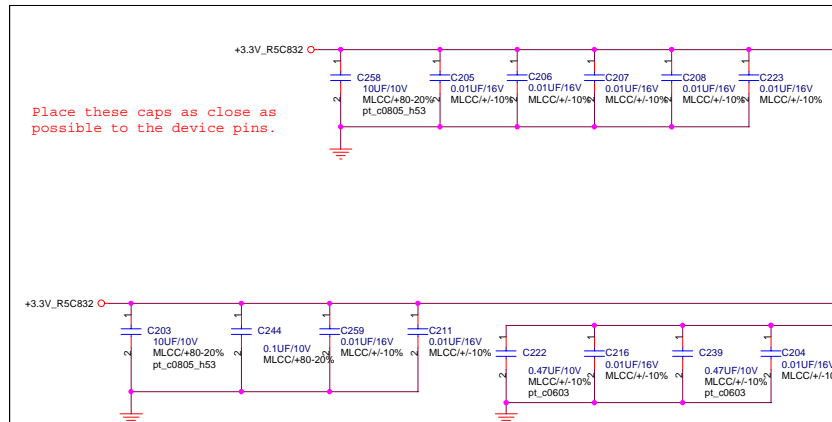
Q9 SI3456BDV-T1-E3  
Q11 2N7002  
Q12 2N7002

R51 100KOhm 5%  
R46 100KOhm 5%  
R58 100KOhm 5%  
R48 100KOhm 5%  
R50 0Ohm  
R52 0Ohm

C57 100PF/50V/X7R  
C319 3800PF/50V/X7R  
C318 3800PF/50V/X7R  
C45 0.1uF/2.5V  
C59 0.1uF/2.5V

[illegible]

SCHEMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER :
RELEASE DATE :		



PROJECT: Lanai	REVISION 1.2	DATE: Monday, March 19, 2007	DESCRIPTION: R5C833 - PCI INTERFACE	SCHEMATIC FILE NAME: <OrgName>	DESIGN ENGINEER:
		SHEET 32 OF 68		RELEASE DATE:	

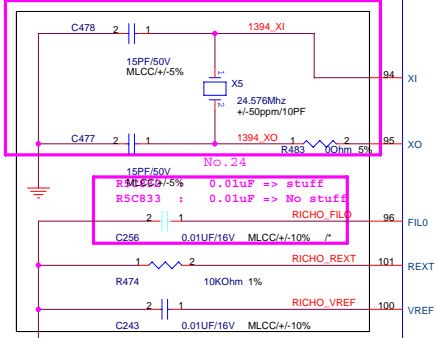
文才专用



# Recommended Crystal Specs from Data Sheet:

Normal Frequency : 24.576 MHz  
Frequency Tolerance : +/- 50ppm @ 25C  
Driver Level : .1 mW  
Load capacitance : 10pF  
Eqv. Resistance : 50 Ohm Max  
Shunt Capacitance : 7.0pF Max

No.25



Place as close to R5C832 as possible.

U31A

1E2E11394/SD

AVCC\_PHY3V\_1  
AVCC\_PHY3V\_2  
AVCC\_PHY3V\_3  
AVCC\_PHY3V\_4

+3.3V\_RUN\_PHY

TPBIAS0

TPBN0

TPBP0

TPAN0

TPAP0

MDIO17

MDIO16

MDIO15

MDIO14

MDIO13

MDIO12

MDIO11

MDIO10

MDIO05

MDIO08

MDIO19

MDIO18

MDIO02

MDIO03

MDIO00

MDIO01

MDIO09

MDIO04

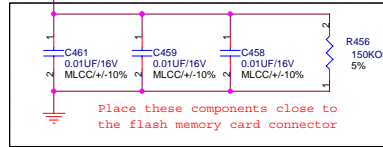
MDIO06

MDIO07

RSV

R5C833 TQFP128  
C.S R5C833 TQFP128

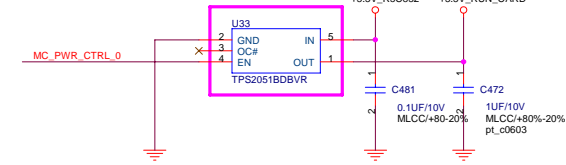
No.24



Place these components close to the flash memory card connector

## For SD/MS Card Power

No.24



+3.3V\_RUN\_CARD

C457

2.2uF/16V  
MLCC +/-10%  
pt\_c0603

SD/XDMS\_CMD

SD/XDMS\_DATA0

SD/XDMS\_DATA1

SD/XDMS\_DATA2

SD/XDMS\_DATA3

SD/XDMS\_DATA4

SD/XDMS\_DATA5

SD/XDMS\_DATA6

SD/XDMS\_DATA7

SD/XDMS\_CMD

SD/XDMS\_DATA0

SD/XDMS\_DATA1

SD/XDMS\_DATA2

SD/XDMS\_DATA3

SD/XDMS\_DATA4

SD/XDMS\_DATA5

SD/XDMS\_DATA6

SD/XDMS\_DATA7

SD/XDMS\_CMD

SD/XDMS\_DATA0

SD/XDMS\_DATA1

SD/XDMS\_DATA2

SD/XDMS\_DATA3

SD/XDMS\_DATA4

SD/XDMS\_DATA5

SD/XDMS\_DATA6

SD/XDMS\_DATA7

SD/XDMS\_CMD

SD/XDMS\_DATA0

SD/XDMS\_DATA1

SD/XDMS\_DATA2

SD/XDMS\_DATA3

SD/XDMS\_DATA4

SD/XDMS\_DATA5

SD/XDMS\_DATA6

SD/XDMS\_DATA7

CON20

TAISOL144-2420000900

SD\_CDSW#

SD\_WP#(XDR/B#)

SD/XDMS\_CLK

SD\_CE#

SD\_CLE

SD\_ALE

SD/XDMS\_CMD

SD\_WP#

SD/XDMS\_DATA0

SD/XDMS\_DATA1

SD/XDMS\_DATA2

SD/XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

SD\_XDMS\_DATA4

SD\_XDMS\_DATA5

SD\_XDMS\_DATA6

SD\_XDMS\_DATA7

SD\_XDMS\_CMD

SD\_XDMS\_DATA0

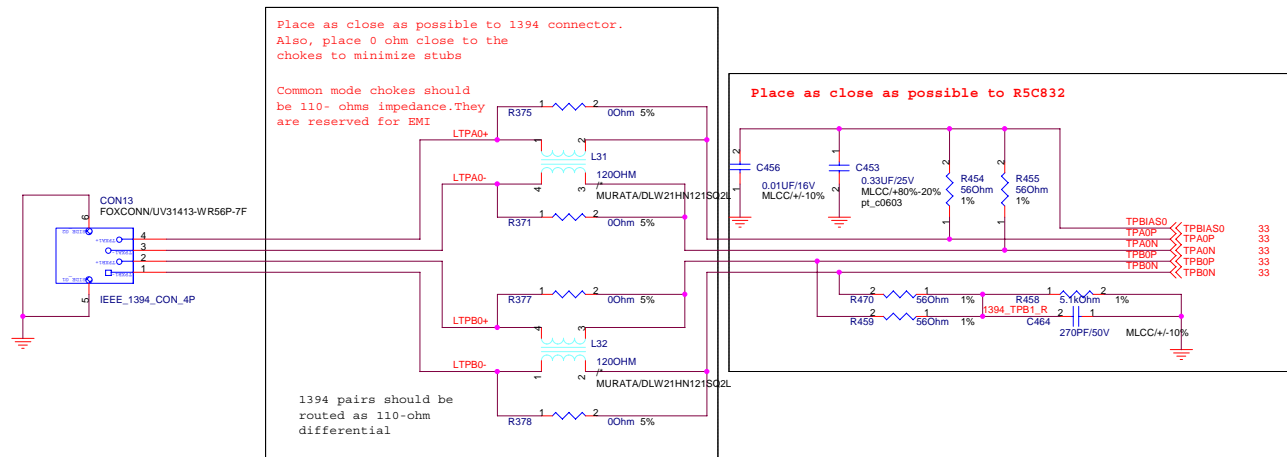
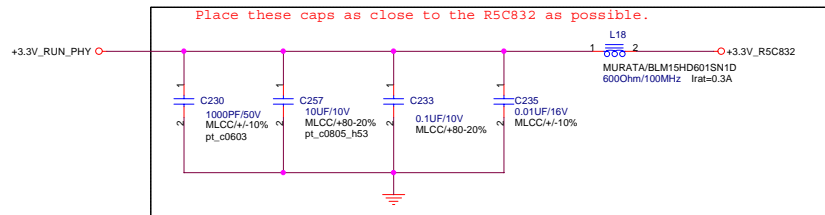
SD\_XDMS\_DATA1

SD\_XDMS\_DATA2

SD\_XDMS\_DATA3

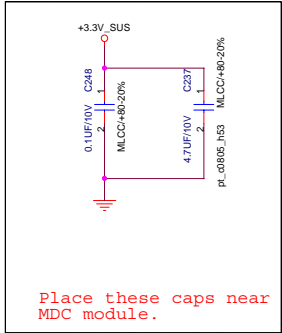
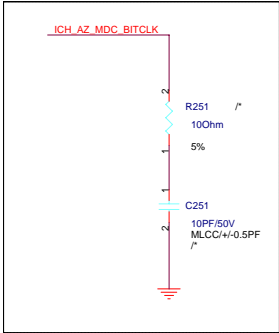
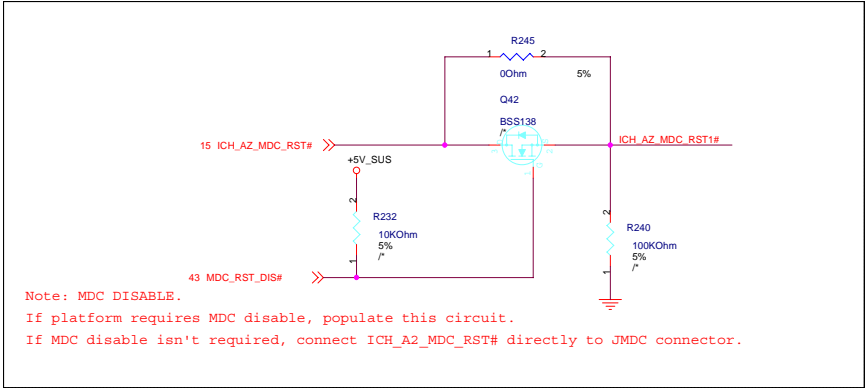
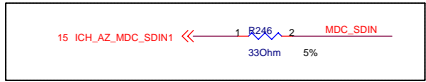
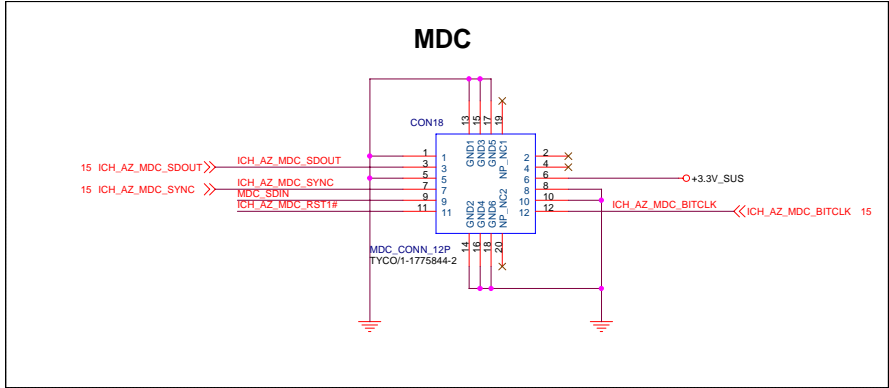
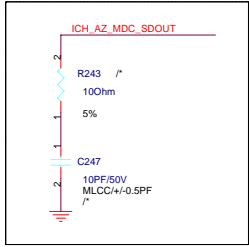
SD\_XDMS\_DATA4

SD\_XDMS\_DATA5



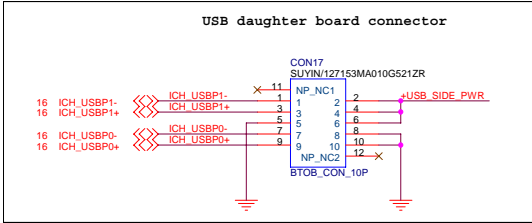
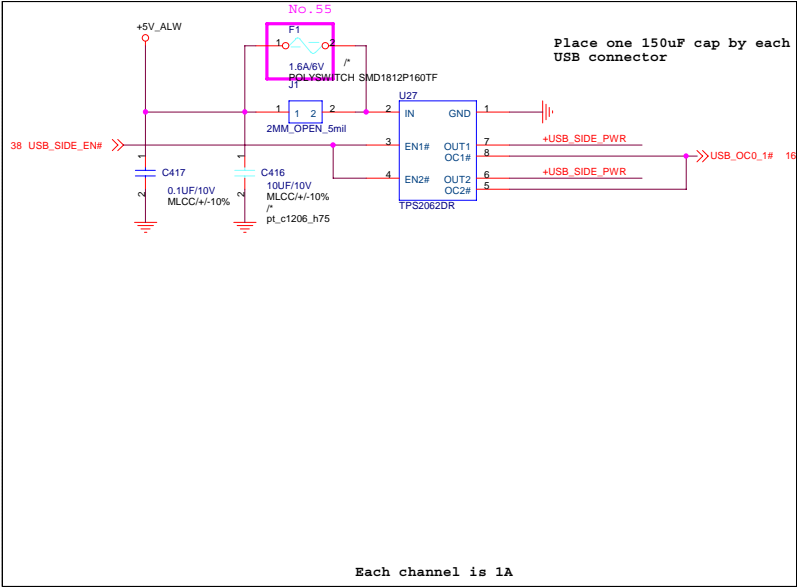
PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: R5C833 - IEEE1394 PART	SCHEMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER :
	1.2	SHEET 34 OF 68		RELEASE DATE :		

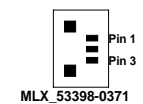
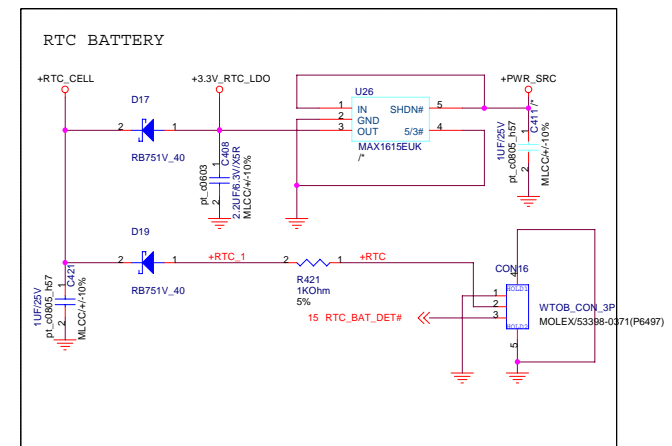






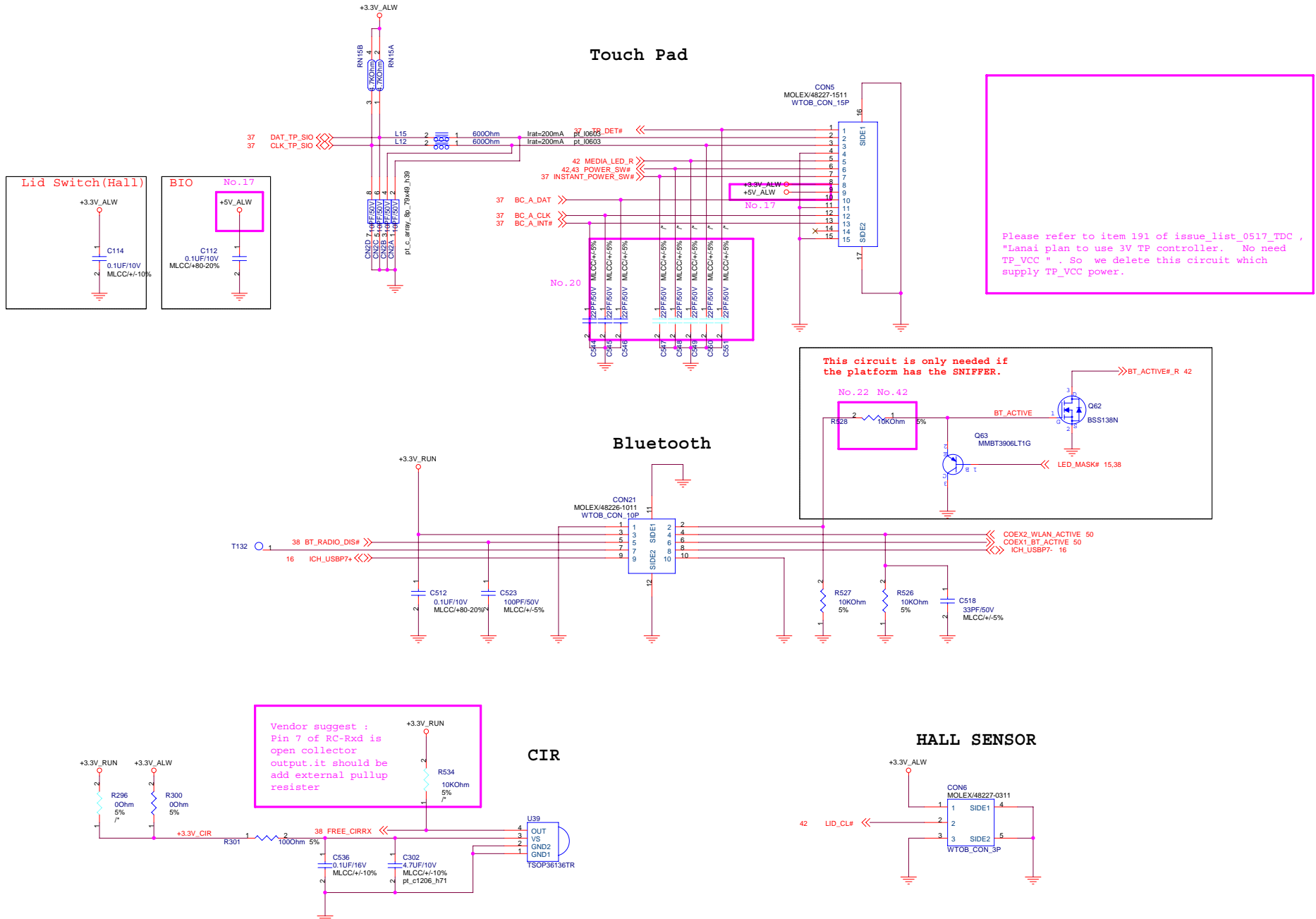




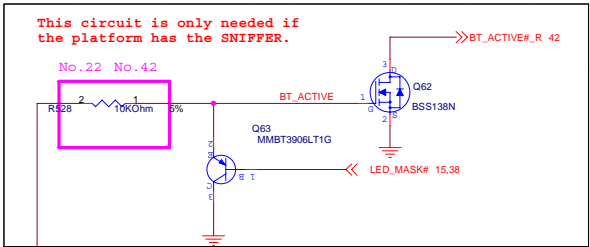


PROJECT: <b>Lanai</b>	REVISION	DATE: <b>Monday, March 19, 2007</b>	DESCRIPTION: <b>FLASH &amp; RTC</b>	SCHEMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER : <b>C.L. Ho</b>
	<b>1.2</b>	SHEET <b>40</b> OF <b>68</b>		RELEASE DATE :		



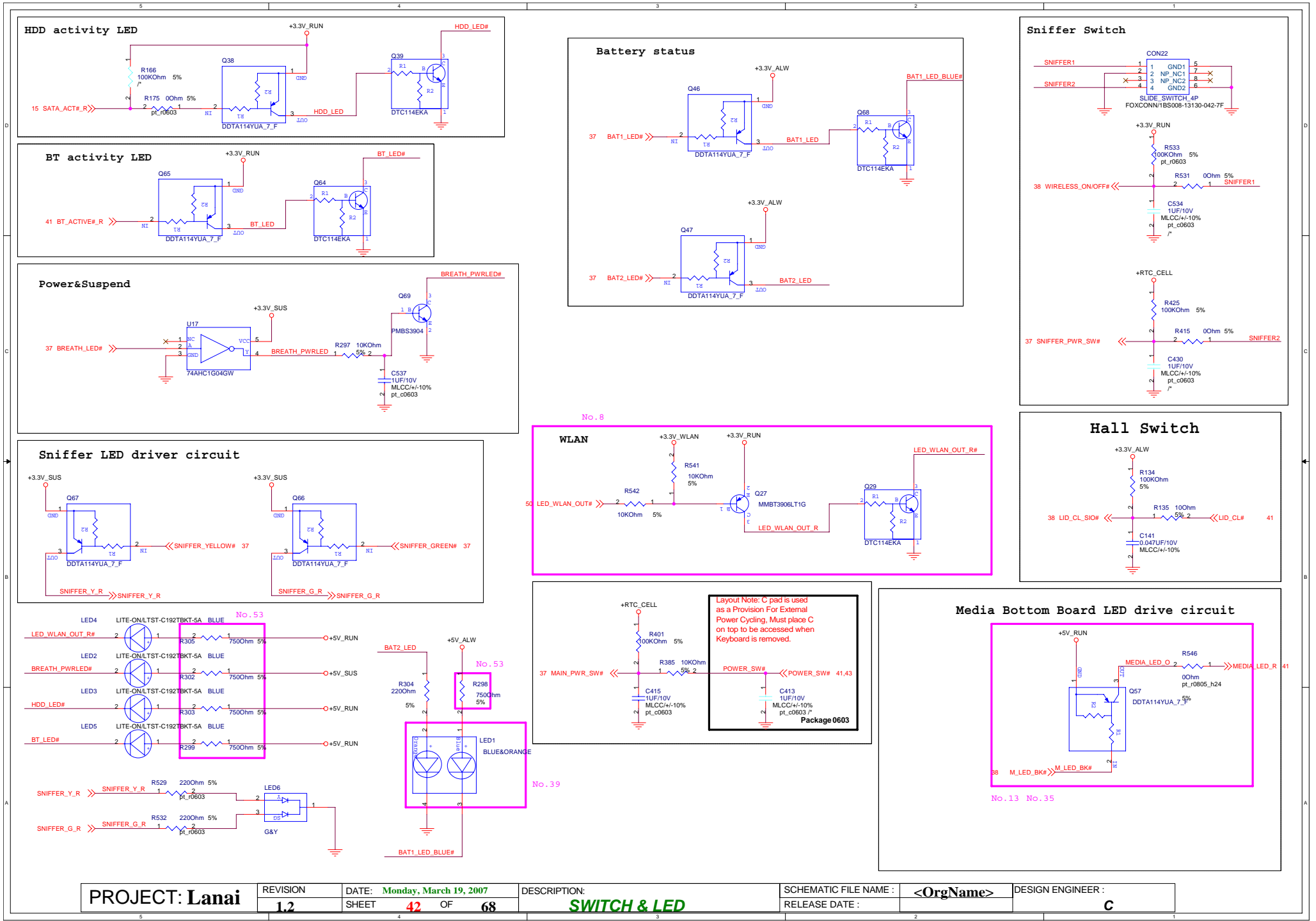


Please refer to item 191 of issue\_list\_0517\_TDC ,  
"Lanai plan to use 3V TP controller. No need  
TP\_VCC ". So we delete this circuit which  
supply TP\_VCC power.



Vendor suggest :  
Pin 7 of RC-Rxd is  
open collector  
output.it should be  
add external pullup  
resister

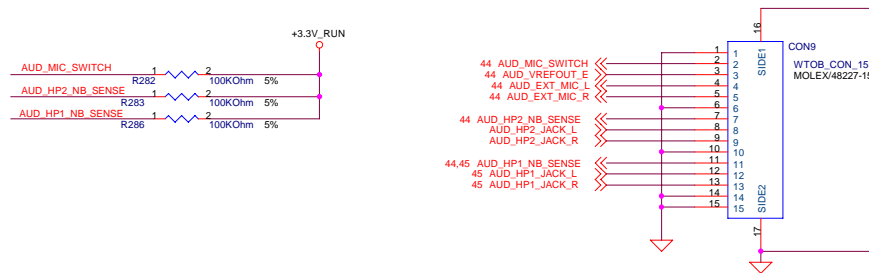
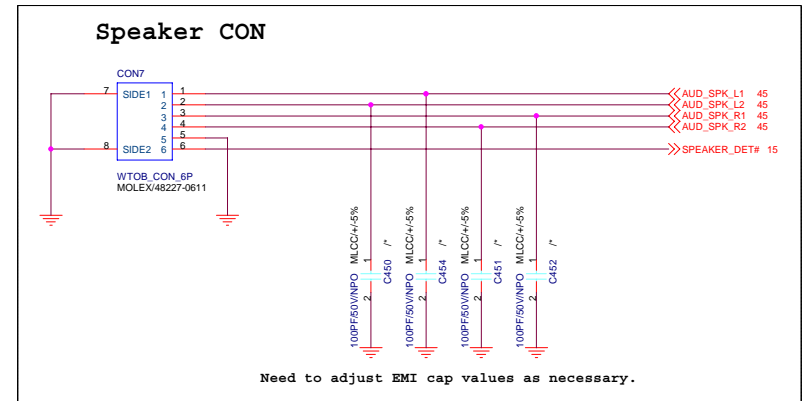
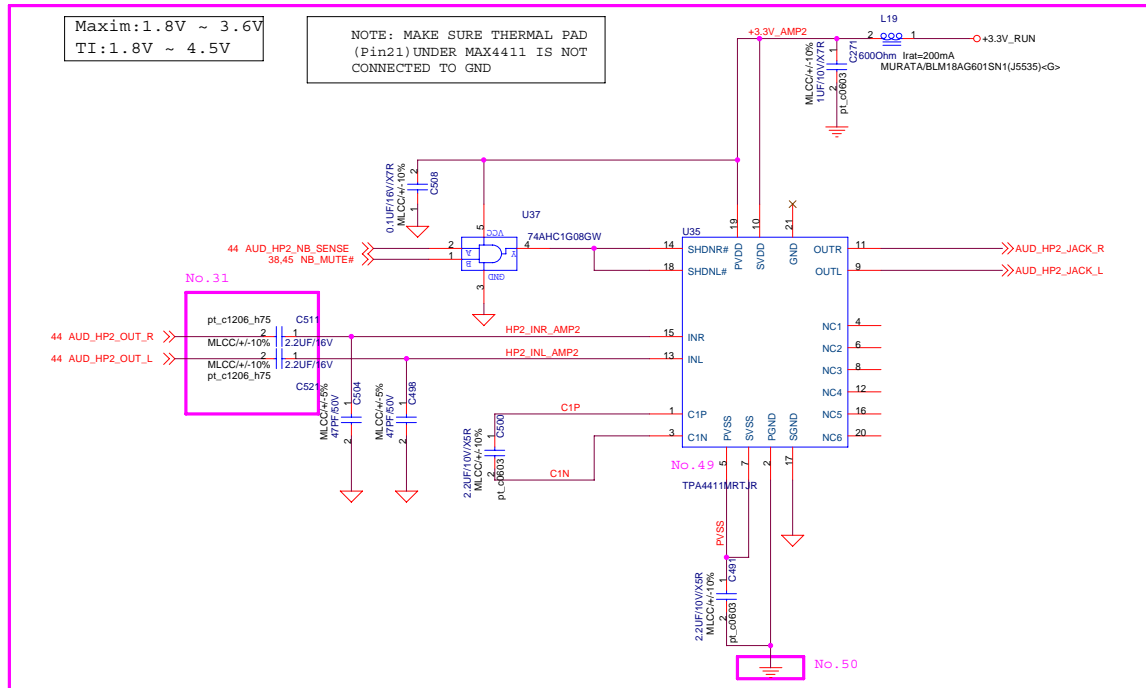
PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: TOUCH PAD & BT & CIR & LID	SCHEMATIC FILE NAME : <OrgName>	DESIGN ENGINEER :
	1.2	SHEET 41 OF 68			



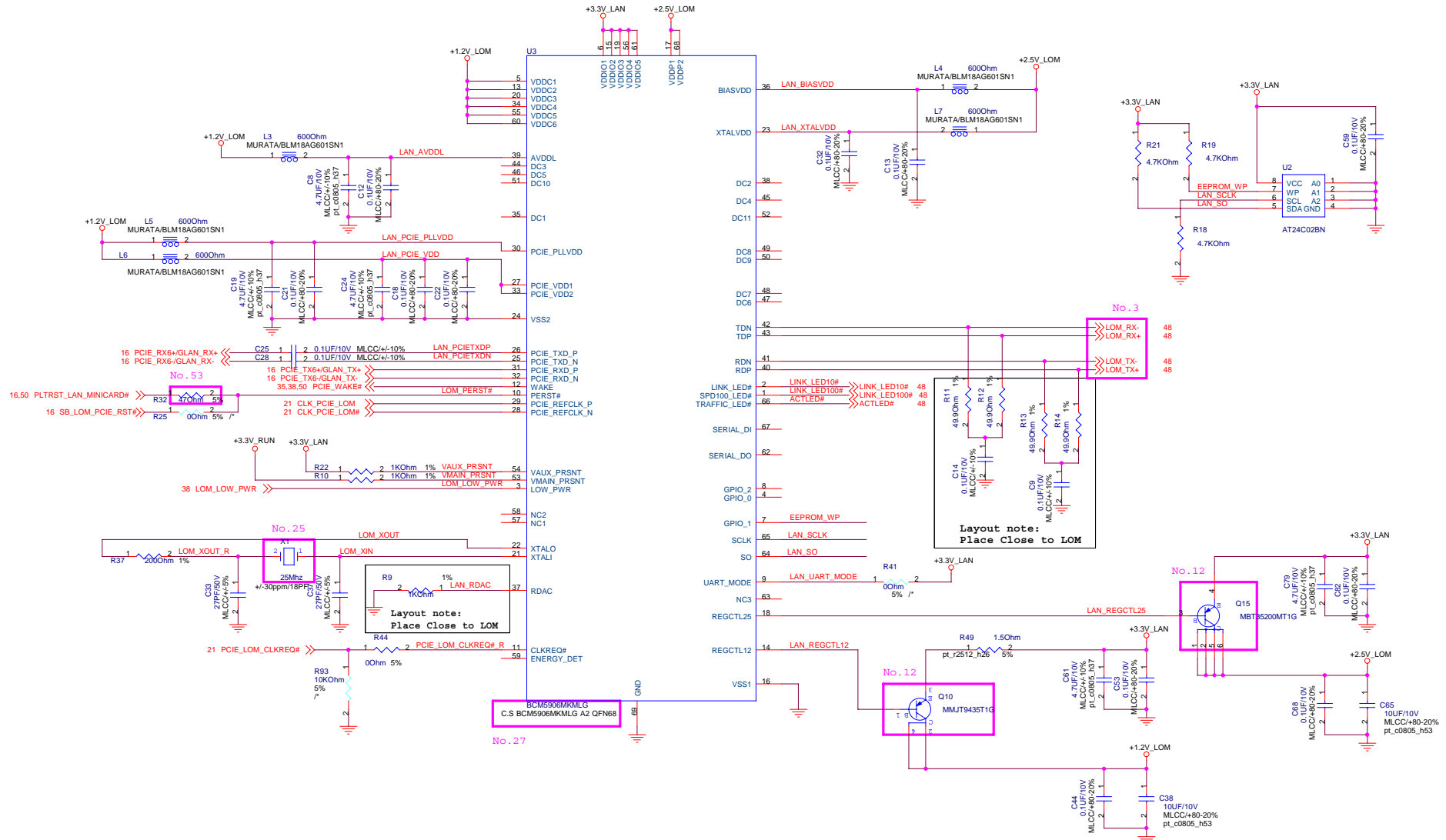
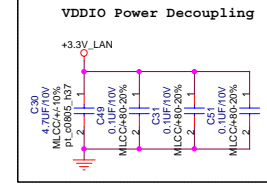
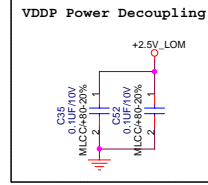
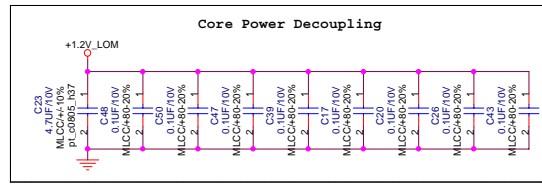




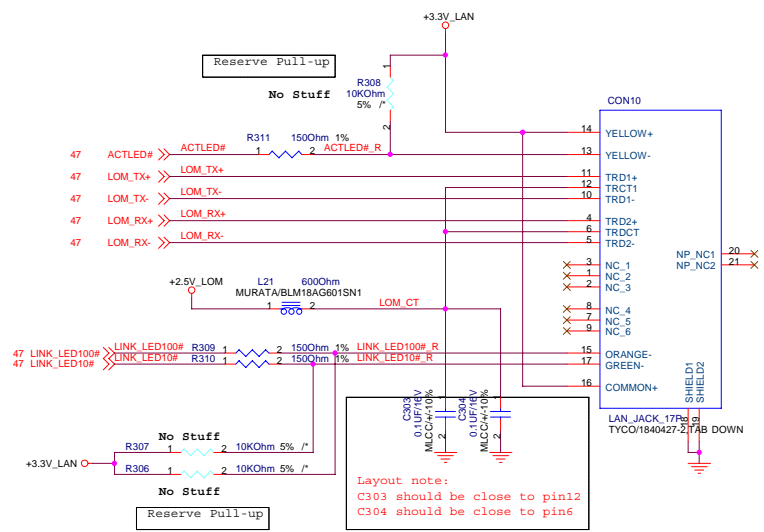




PROJECT: Lanai	REVISION 1.2	DATE: Monday, March 19, 2007	DESCRIPTION: AMP MAX4411 & AUDIO JACK	SCHEMATIC FILE NAME : <OrgName>	DESIGN ENGINEER : Yihao Yeh
	SHEET 46 OF 68			RELEASE DATE :	

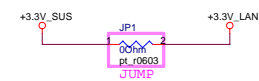


PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: LAN BCM5906M KMLG (QFN68)	SCHEMATIC FILE NAME: <OrgName>	DESIGN ENGINEER: Ivan Chou
	1.2	SHEET 47 OF 68			



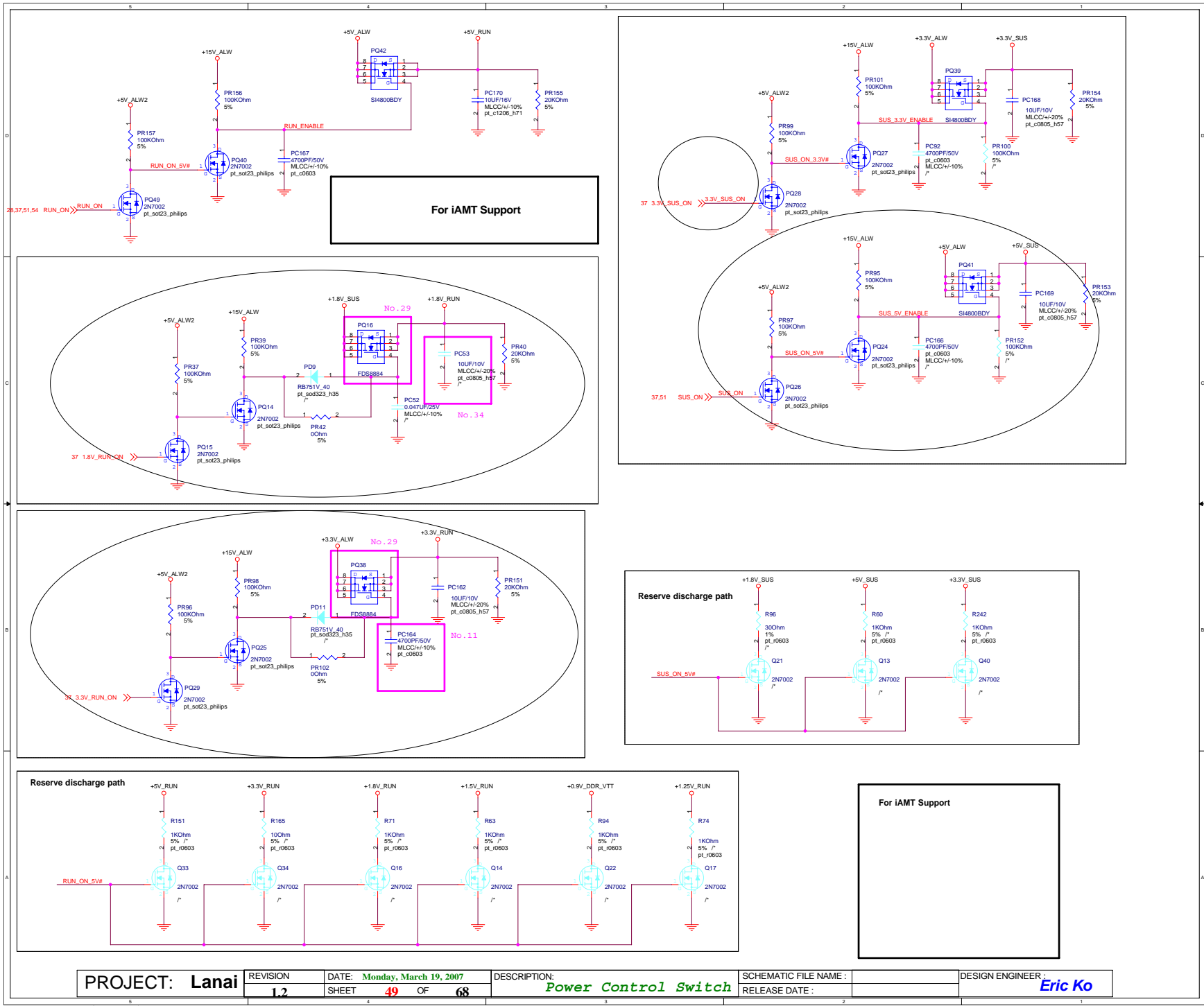
**+3.3V LAN Source Guideline:**

- 1. Use +3.3V\_SUS if Wake-on-LAN is NOT required out of S4, S5
- 2. Use +3.3V\_SRC if Wake-on-LAN is required out of S4, S5

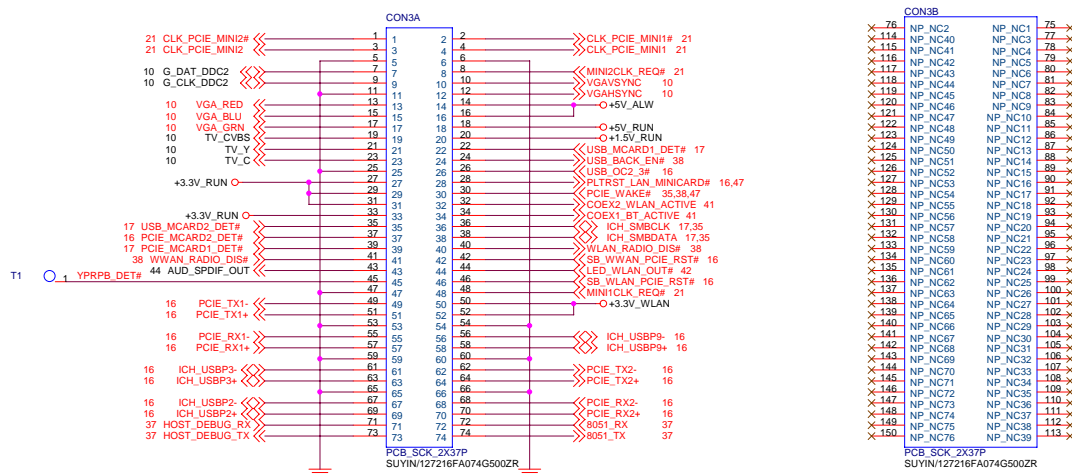
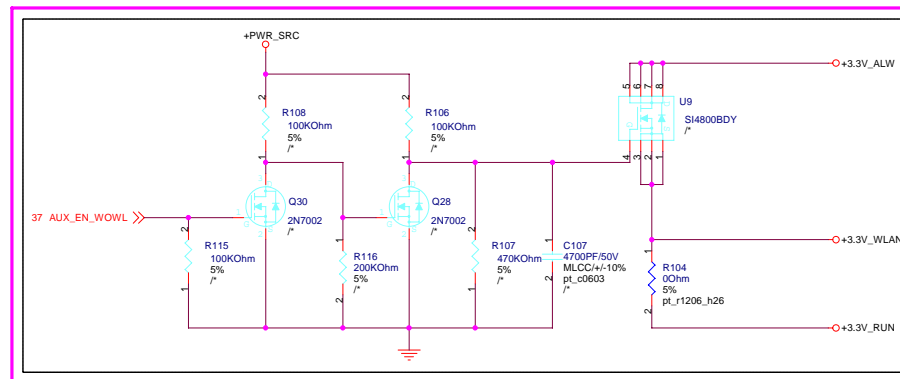


PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: Magnetics and RJ-45	SCHEMATIC FILE NAME : <OrgName>	DESIGN ENGINEER : Ivan Chou
	1.2	SHEET 48 OF 68			





No. 21



PROJECT: Lanai

REVISION  
1.2

DATE: Monday, March 19, 2007  
SHEET 50 OF 68

DESCRIPTION: BtoB CON

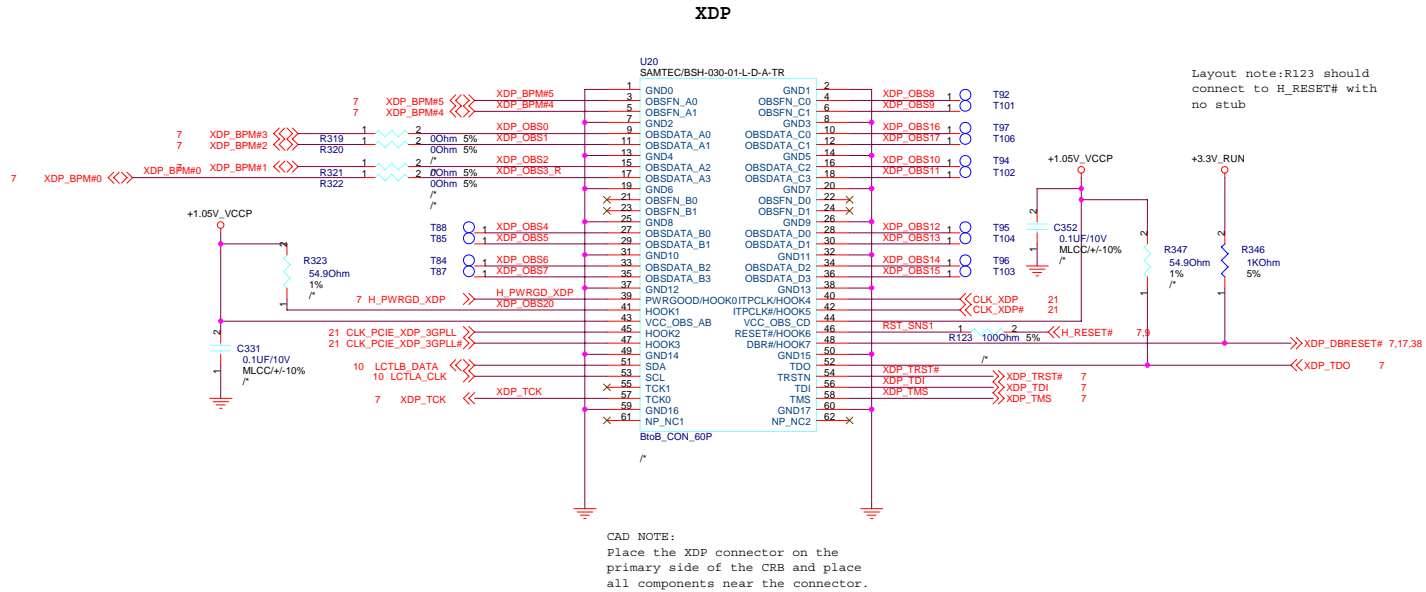
SCHEMATIC FILE NAME :  
RELEASE DATE :

<OrgName>

DESIGN ENGINEER :  
STANLY HSU

文才专用



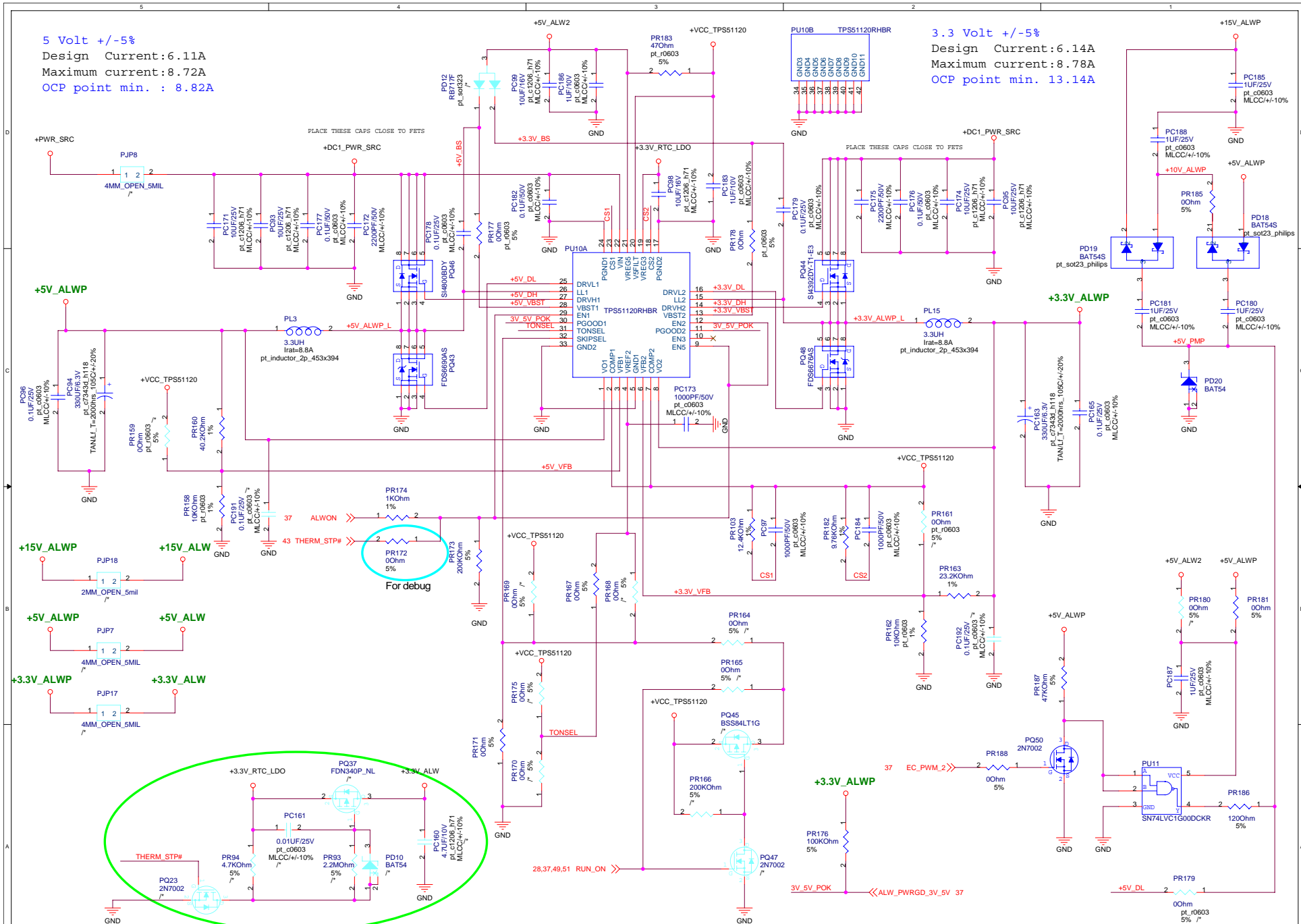


PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: XDP	SCHEMATIC FILE NAME: <OrgName>	DESIGN ENGINEER: Terry Lin
	1.2	SHEET 52 OF 68			



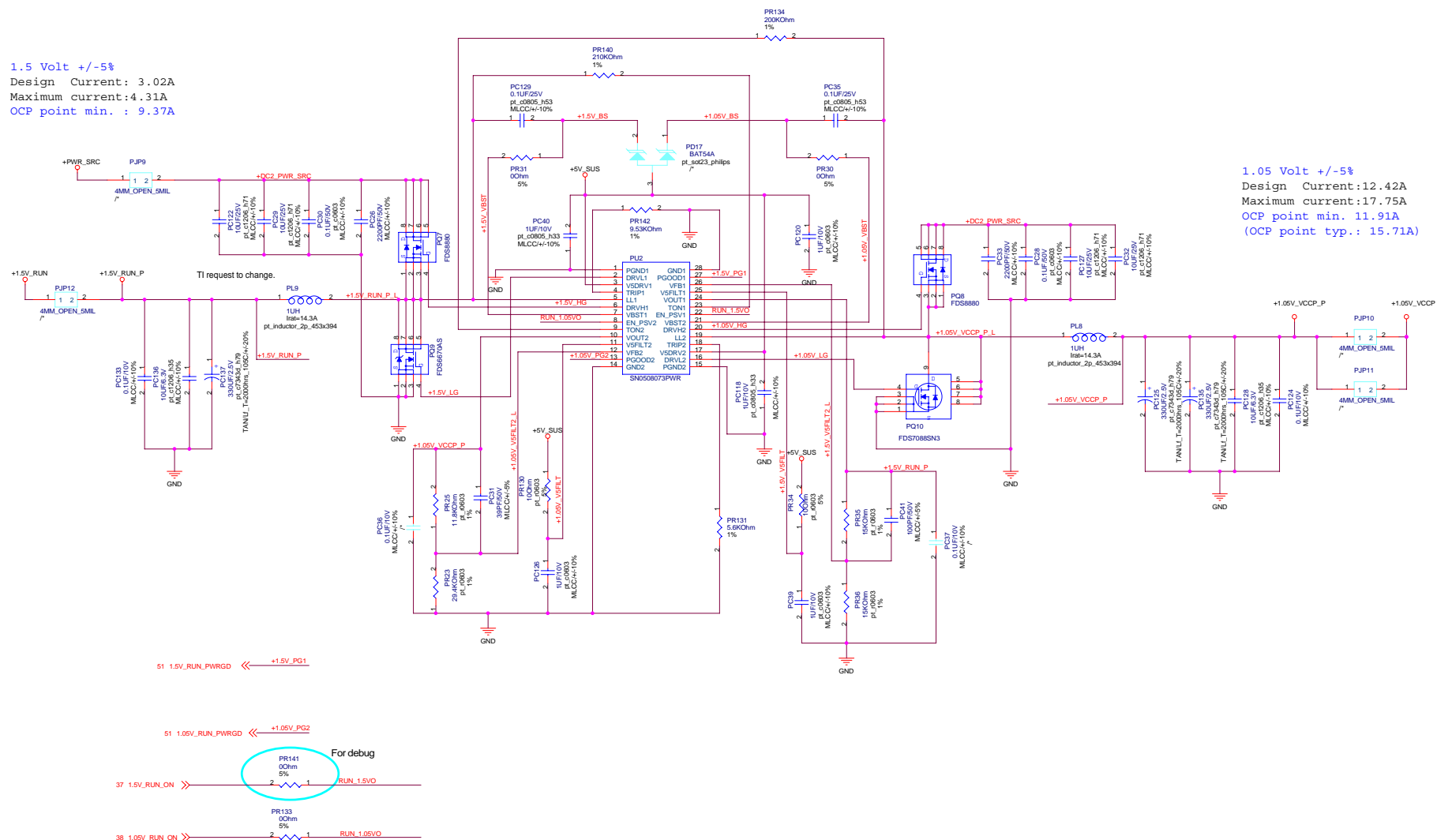
5 Volt +/-5%  
Design Current:6.11A  
Maximum current:8.72A  
OCP point min. : 8.82A

3.3 Volt +/-5%  
Design Current:6.14A  
Maximum current:8.78A  
OCP point min. 13.14A



PROJECT: <b>Lanai</b>	REVISION	DATE: <b>Monday, March 19, 2007</b>	DESCRIPTION: <b>POWER_SYSTEM5V_ALW&amp;3.3V_ALW</b>	SCHMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER : <b>JEFF</b>
	<b>1.2</b>	SHEET <b>54</b> OF <b>68</b>		RELEASE DATE :		

1.5 Volt +/-5%  
Design Current: 3.02A  
Maximum current:4.31A  
OCP point min. : 9.37A



1.05 Volt +/-5%  
Design Current:12.42A  
Maximum current:17.75A  
OCP point min. 11.91A  
(OCP point typ.: 15.71A)

PROJECT: <b>Lanai</b>	REVISION	DATE: <b>Monday, March 19, 2007</b>	DESCRIPTION:	SCHEMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER :
	<b>12</b>	SHEET <b>55</b> OF <b>68</b>	<b>POWER I/O 1.5VS &amp; 1.05VS</b>	RELEASE DATE :		<b>JEFF</b>





TOTAL POWER=65W  
-->3.34A

TABLE3 PIN NAME DIFFERENCES		
PIN	MAXIM	INTERSIL
1	GND	NC
3	REF	VREF
4	CCS	ICOMP
5	CCI	NC
6	CCV	VCOMP
7	DAC	NC
8	IINP	ICM
11	VDD	VDDSMB
14	BATSEL	NC
15	FBSA	VFB
16	FBSB	NC
17	CSIN	CSOP
18	CSIP	CSOP
20	DLO	LGATE
21	LDO	VDDP
23	LX	PHASE
24	DHI	UGATE
25	BST	BOOT
"NC" means no-connect		

Charge Current:4.68A  
Discharge current:6.6A

TABLE2 MAXIM & INTERSIL BOM DIFFERENCES		
REF DES	MAXIM	INTERSIL
PR125	8.45K, 0402, 1%	16.0K, 0402, 1%
PC115	0.01uF	No Stuff
PC17	0.1uF, 0402, 10V	No Stuff
PC24	1.0uF, 0603, 10V	No Stuff
PR106	365K, 0402, 1%	215K, 0402, 1%
PR8	0, 0402, 5%	10, 0402, 5%
PR21	0, 0402, 5%	10, 0402, 5%
PC4	No Stuff	0.22uF
PC19	No Stuff	0.22uF
PC22	0.01uF	No Stuff
PC18	0.1uF, 0402, 10V	No Stuff
PC8	220pF, 0402, 50V	No Stuff
PD16	RB751V-40	No Stuff
PC13	3.3nF	No Stuff
PR19	1, 0603, 1%	0, 0603, 5%
PR9	100, 0402, 5%	0, 0402, 5%
PR22	4.7K, 0402, 5%	4.7K, 0402, 5%
PC23	0.01uF	0.01uF
PC21	0.01uF	0.01uF
PD3	1SS355	No stuff
PR12	1K, 0603, 5%	No stuff

TABLE1				
ADAPTOR (W)	TRIP CURRENT (A)	PR121	PR123	PR126 PR122
65	3.17	57.6K	13.0K	105 N/A
90	4.43	51.1K	17.8K	348 33.2K
130	6.43	32.4K	20.5K	100 27.4K
150	7.43	30.9K	24.9K	432 88.7K
200	9.75	19.1K	28K	301 36.5K
230	11.28	32.4K	6.49K	115 N/A

Note 1: PR122 is populated if ADAPT TRIP SET is used to program for the next lower adaptor  
ADAPT TRIP SET is floating for the higher adaptor, grounded for the lower adaptor  
Note 2: 24.9K at PR122 allows the 65W adaptor setting to switch down to 45W. (now is N/A)  
Note 3: PR109 must be 5m ohm instead of 10m ohm for the 230W adaptor

PROJECT: Lanai

REVISION  
1.2

DATE: Monday, March 19, 2007  
SHEET 57 OF 68

DESCRIPTION: POWER CHARGER

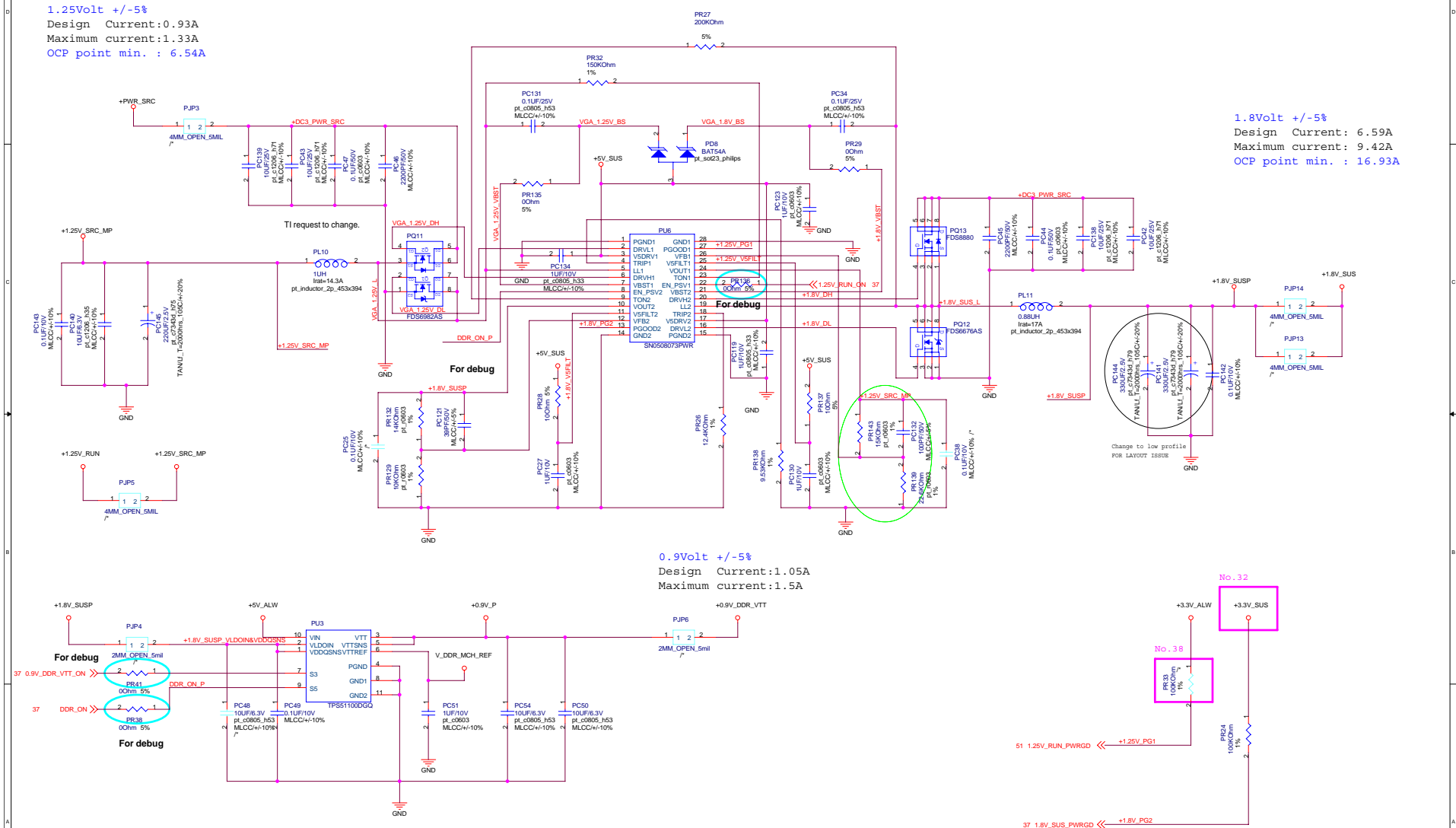
SCHEMATIC FILE NAME: <OrgName>  
RELEASE DATE:

DESIGN ENGINEER: JEFF

1.25Volt +/-5%  
Design Current:0.93A  
Maximum current:1.33A  
OCP point min. : 6.54A

1.8Volt +/-5%  
Design Current: 6.59A  
Maximum current: 9.42A  
OCP point min. : 16.93A

0.9Volt +/-5%  
Design Current:1.05A  
Maximum current:1.5A



PROJECT: Lanai

REVISION  
1.2

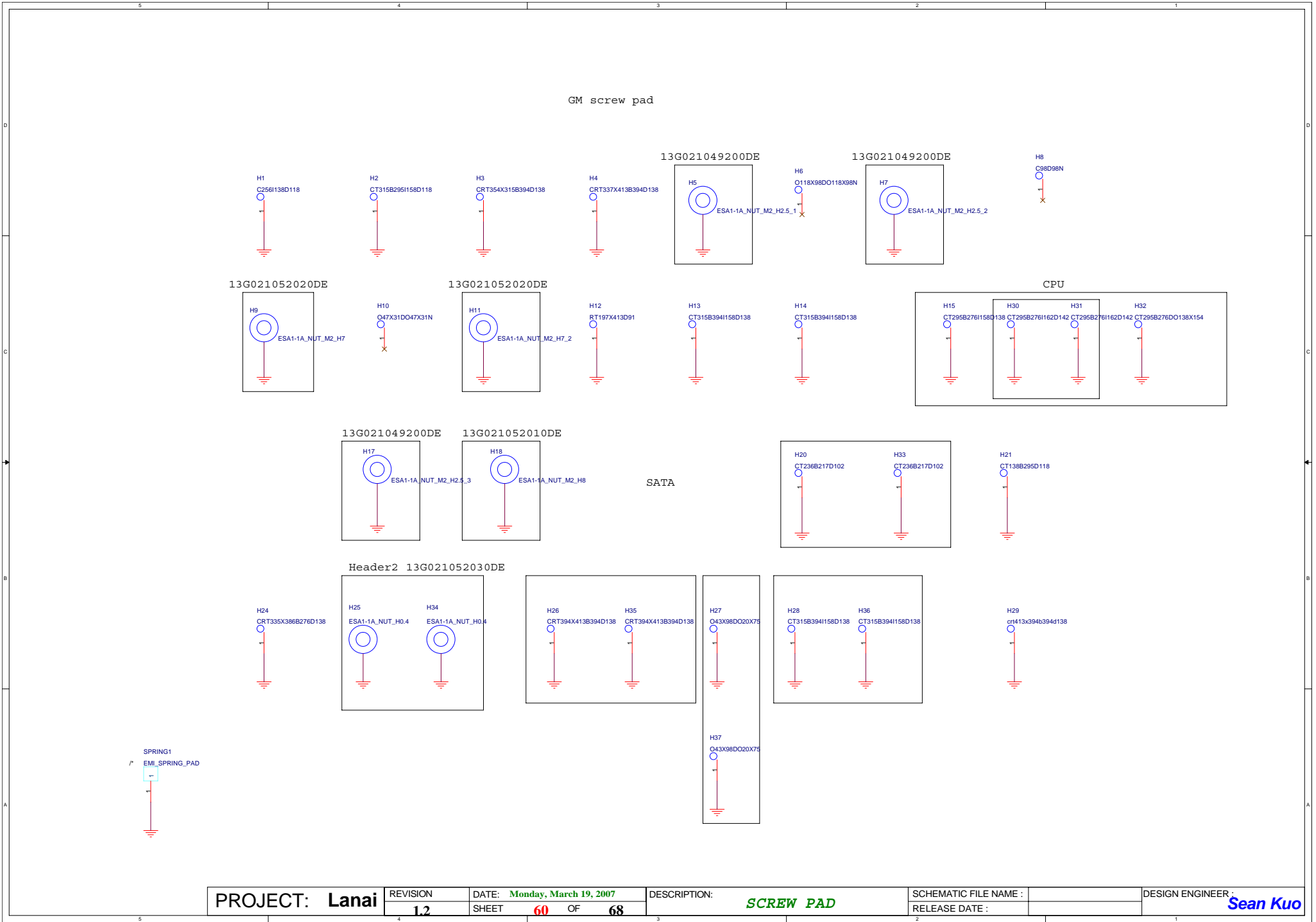
DATE: Monday, March 19, 2007  
SHEET 58 OF 68

DESCRIPTION:  
POWER VGA 1.25V & DDR & VTT

SCHEMATIC FILE NAME: <OrgName>  
RELEASE DATE:

DESIGN ENGINEER:  
Jeff





PROJECT: Lanai

REVISION  
1.2

DATE: Monday, March 19, 2007  
SHEET 60 OF 68

DESCRIPTION: SCREW PAD

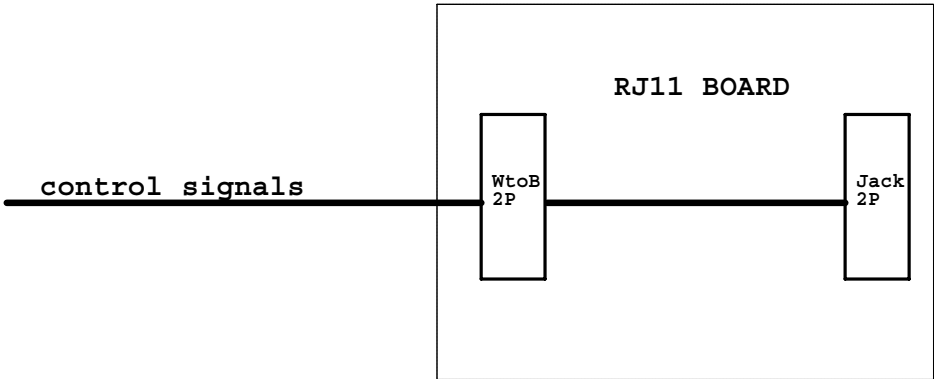
SCHEMATIC FILE NAME :  
RELEASE DATE :

DESIGN ENGINEER : Sean Kuo

ASUS CONFIDENTIAL

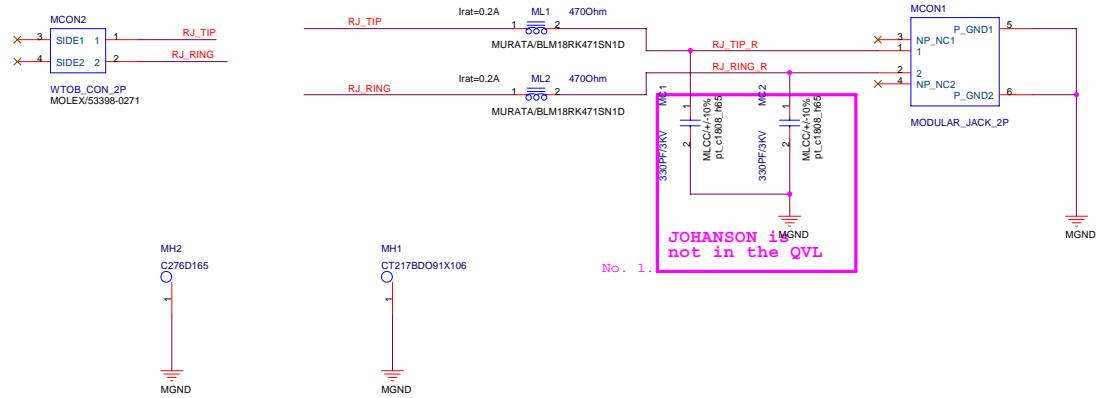
MODEL NAME : *Elsa*

*Lanai:Modem Board*



**REV : 1.1(DELL: X01)**

PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: <i>BLOCK DIAGRAM</i>	SCHEMATIC FILE NAME :	DESIGN ENGINEER : <i>Stanly Hsu</i>
	1.2	SHEET 64 OF 68		RELEASE DATE :	



PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION: RJ-11 CONN	SCHEMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER : Stanly Hsu
	1.2	SHEET 65 OF 68		RELEASE DATE :		

ASUS CONFIDENTIAL

MODEL NAME : *Elsa*  
PCB NO : *???*  
ASUS P/N : *???*

Lanai PP2 USB Board

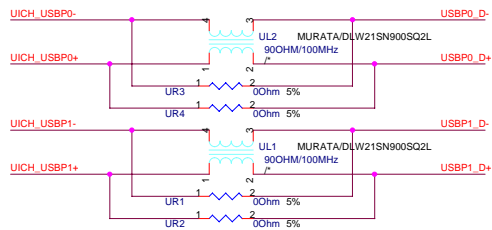
REV : 1.1(DELL: X01)

MB PCB	
Part Number	Description
DA800004H0L	PCB 00B LA-3071P REV0 M/B

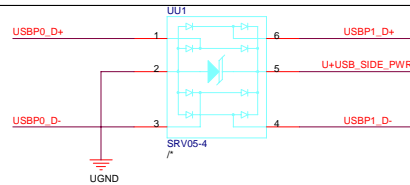
*BOM NO. ???*  
*PCB P/N: ???*

PROJECT: <b>Lanai</b>	REVISION	DATE: <i>Monday, March 19, 2007</i>	DESCRIPTION: <i>Cover Page</i>	SCHEMATIC FILE NAME :	DESIGN ENGINEER :
	<b>1.2</b>	SHEET <b>67</b> OF <b>68</b>		RELEASE DATE :	<i>Terry Lin</i>

External USB PORT hookup reference. Your design may need more or less external ports and may be mapped differently .

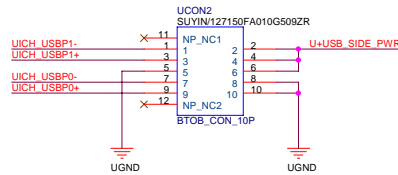


Platforms should put in PADS for the USB chokes if they have the room. Chokes should be NOPOP.

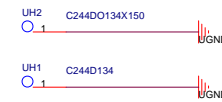


Place ESD diodes as close as USB connector. Semtech SRV05-4 can also be used but the Philips IP42220CZ6 have a lower input C ( 1pf vs 3pf ) .

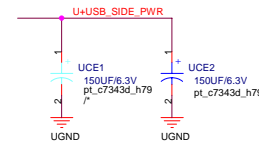
#### USB daughter board connector



#### Screw hole

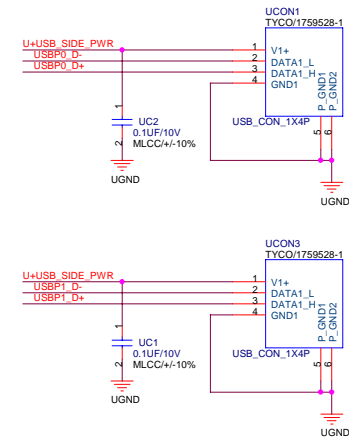


Place one 150uF cap by each USB connector



Each channel is 1A

Consult you ESD Engineer if you think you may need to add ESD Supression Components to your USB lines. Add PADS ONLY until proven diodes are really needed.



PROJECT: Lanai

REVISION  
1.2

DATE: Monday, March 19, 2007  
SHEET 68 OF 68

DESCRIPTION:  
USB PORT ( SINGLE \* 2 )

SCHEMATIC FILE NAME :  
RELEASE DATE :

<OrgName>

DESIGN ENGINEER :  
Terry Lin